

# IEEE P802.3bs Baseline Summary

John D'Ambrosia, Dell  
Chair, IEEE P802.3bs 400 GbE Task Force

July 11, 2015  
(Post May, 2015 Summary)

Topic Matter	Motion	Reference Presentation
Architecture	<ul style="list-style-type: none"> <li>Motion #3, Jan 15: Move to adopt slides 4 and 8 from dambrosia_3bs_02b_0115 as baseline architecture.</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_01/dambrosia_3bs_02b_0115.pdf">http://www.ieee802.org/3/bs/public/15_01/dambrosia_3bs_02b_0115.pdf</a>
RS / CDMII	<ul style="list-style-type: none"> <li>Motion #3, July 14: Move to adopt the baseline for the CDMII logical interface as shown in slide 5 of gustlin_3bs_03_0714.pdf.</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/14_07/gustlin_3bs_03_0714.pdf">http://www.ieee802.org/3/bs/public/14_07/gustlin_3bs_03_0714.pdf</a>
FEC	<ul style="list-style-type: none"> <li>Motion #3, Mar 15: Move to adopt RS(544,514,10) as the FEC in the 802.3bs 400GbE architecture</li> </ul>	
Electrical Interfaces (C2C and C2M)	<ul style="list-style-type: none"> <li>Motion #4, Sept 14: Move to adopt 16 x 25Gb/s and 8 x 50Gb/s as the basis for the lane rates for any optional C2C and C2M electrical interfaces</li> </ul>	
C2C / C2M 25G Electrical	<ul style="list-style-type: none"> <li>Motion #6, Sept 14: Move to adopt the P802.3bm C2C and C2M specifications with current values (except that the BER requirement is TBD) as a baseline draft for the 16 x 25Gb/s electrical interfaces</li> </ul>	
C2C 50G Electrical	<ul style="list-style-type: none"> <li>Motion #4, Mar 15: Move to adopt li_3bs_01a_0315.pdf as the baseline proposal for CDAUI-8 chip-to-chip electrical I/O interface except for the differential return losses (on slide 11) for the TX and the RX shall be TBD .</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_03/li_3bs_01a_0315.pdf">http://www.ieee802.org/3/bs/public/15_03/li_3bs_01a_0315.pdf</a>
C2M 50G Electrical	<ul style="list-style-type: none"> <li>Motion #5, Mar 15: Move to adopt brown_3bs_01a_0315.pdf as the baseline proposal for CDAUI-8 chip-to-module electrical I/O interface.</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_03/brown_3bs_01a_0315.pdf">http://www.ieee802.org/3/bs/public/15_03/brown_3bs_01a_0315.pdf</a>
C2C Informative Channel	<ul style="list-style-type: none"> <li>Motion #6, Jan 15: Move to adopt the following equation as the informative insertion loss equation for CDAUI-8 chip-to-chip electrical I/O interface  <math display="block">IL \leq \{ 1.083 + 2.543\sqrt{f} + 0.761f \quad 0.01 \leq f \leq 28.05\text{GHz} \} \text{ dB}</math> </li> </ul>	
C2M Informative Channel	<ul style="list-style-type: none"> <li>Motion #8, Jan 15: Move to adopt the following equation as the informative insertion loss equation for CDAUI-8 chip-to-module electrical I/O interface  <math display="block">IL \leq \{ 1.076(0.075 + 0.537\sqrt{f}) + 0.566f \quad 0.01 \leq f \leq 28.05\text{GHz} \} \text{ dB}</math> </li> </ul>	

EEE	<ul style="list-style-type: none"> <li>• Motion #4, Jan 15: Move to adopt the EEE baseline proposed in marris_3bs_01_0115.pdf slide 7.</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_01/marris_3bs_01_0115.pdf">http://www.ieee802.org/3/bs/public/15_01/marris_3bs_01_0115.pdf</a>
OTN	<ul style="list-style-type: none"> <li>• Motion #5, Jan 15: Move to adopt slide 10 of trowbridge_3bs_01a_0115.pdf as the baseline for the OTN mapping reference point</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_01/trowbridge_3bs_01a_0115.pdf">http://www.ieee802.org/3/bs/public/15_01/trowbridge_3bs_01a_0115.pdf</a>
100m MMF	<ul style="list-style-type: none"> <li>• Motion #3, Nov 14: Move to adopt the proposal in slides 6 to 16 in king_3bs_02a_1114.pdf as the baseline proposal for the P802.3bs objective to “provide physical layer specifications which support link distances of at least 100 m of MMF” (400GBASE-SR16)*</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/14_11/king_3bs_02a_1114.pdf">http://www.ieee802.org/3/bs/public/14_11/king_3bs_02a_1114.pdf</a>
500m SMF	<ul style="list-style-type: none"> <li>• Motion #12, May 15: Move to adopt 4x100G PAM4 PSM4 as the modulation format for the 500m SMF (single mode fiber) PMD objective</li> </ul>	
10km SMF	<ul style="list-style-type: none"> <li>▪ Motion #4, July 14: Move that 10km 400GbE SMF PMD will use a duplex fiber solution.</li> <li>▪ Motion #6, May 15: Move to adopt 8 lambda x 50 Gb/s as the basis for the 10 km SMF PMD objective</li> <li>▪ Motion #9, May 15: Move to adopt 8x50G PAM4 as the modulation format for the 10km SMF (single mode fiber) PMD objective</li> <li>▪ Motion #11, May 15: Move to adopt a baseline for the 10km SMF PMD objective based on the 10km proposal in cole_3bs_01a_0515</li> </ul>	<a href="http://www.ieee802.org/3/bs/public/15_05/cole_3bs_01a_0515.pdf">http://www.ieee802.org/3/bs/public/15_05/cole_3bs_01a_0515.pdf</a>

# 400GbE Architecture Baseline Proposal (Update)

**IEEE P802.3bs 400 Gb/s Ethernet Task Force**

January 2015

Pete Anslow - Ciena  
John D'Ambrosia – Dell  
Mark Gustlin – Xilinx  
Adam Healey – Avago  
David Law – HP  
Gary Nicholl - Cisco  
Dave Ofelt – Juniper  
Steve Trowbridge - ALU

# What Needs to be Supported in the Architecture?

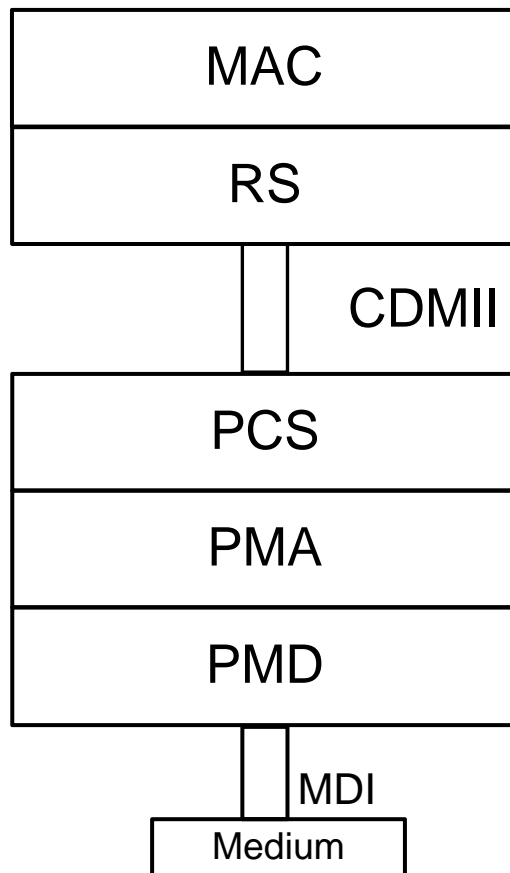
- The coding needs of the electrical interface may vary independently from the PMD interface
- The requirements for each interface can be different, both the FEC, modulation and number of lanes can change over time for each interface
- We need a single high level architecture which can support the evolving requirements of the interfaces over time
  - This does not mean it requires a complicated implementation
- A Media Independent interface needs to be specified to enable standardization of different PHYs today and future, “unknown”, PHYs tomorrow.
- We need an electrical interface between different devices, CDAUI (C2C & C2M)
- IEEE 802.3 supports two “levels” of implementers
  - The system implementer
  - The component implementer

## Sublayer Functions (at a high level)

Sublayer	10GbE	100GbE	400GbE (proposed)
MAC	Framing, addressing, error detection	Framing, addressing, error detection	Framing, addressing, error detection
Extender	XGXS (PCS + PMA function)	N/A	CDXS (PCS + FEC function)
PCS	Coding (X: 8B/10B, R: 64B/66B), lane distribution, EEE	Coding (64B/66B), lane distribution, EEE	Coding, lane distribution, EEE, FEC
FEC	FEC, transcoding	FEC, transcoding, align and deskew	N/A
PMA	Serialization, clock and data recovery	Muxing, clock and data recovery, HOM	Muxing, clock and data recovery, HOM??
PMD	Physical interface driver	Physical interface driver	Physical interface driver

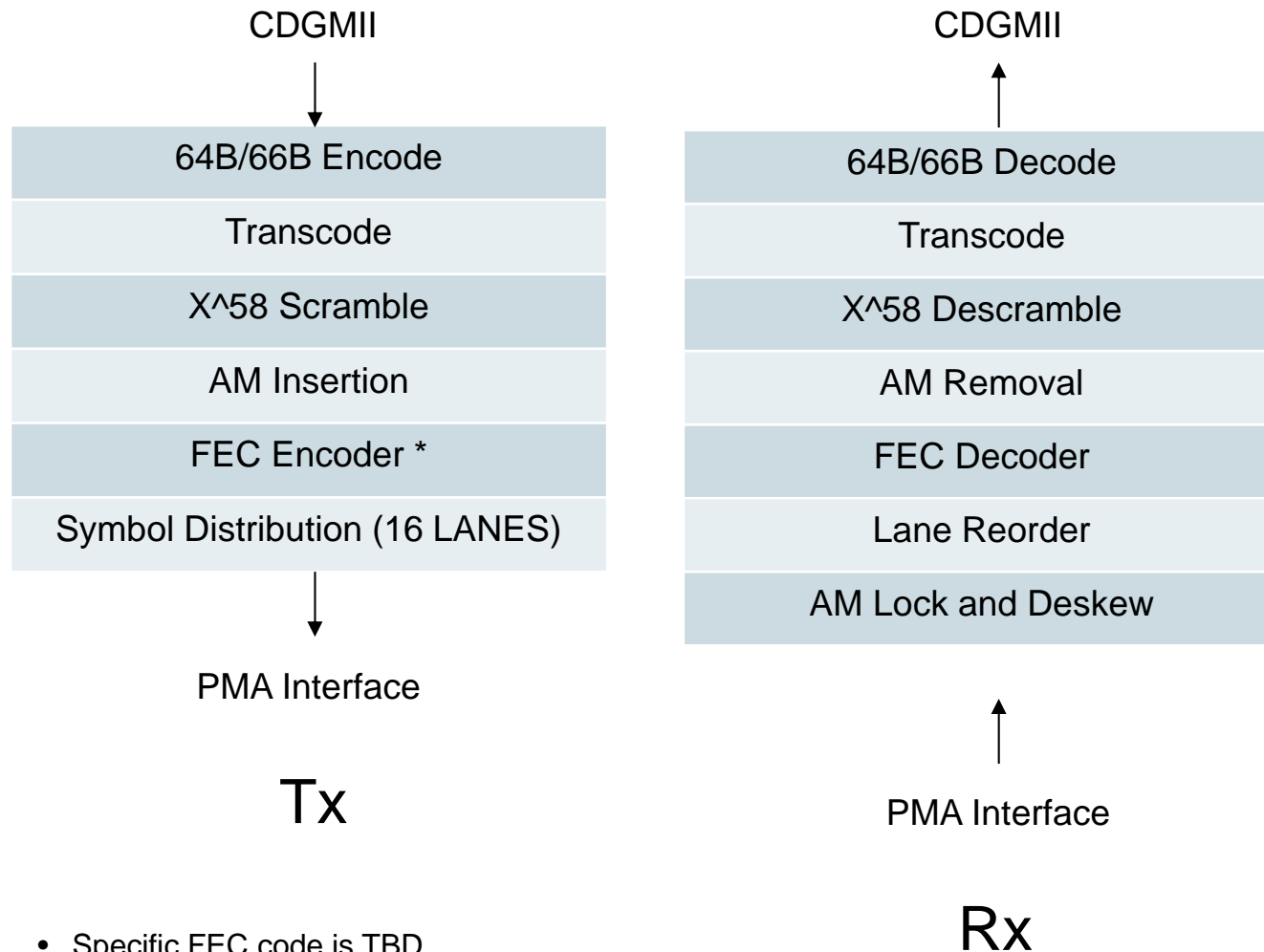
Note that there are variations with a single speed, not all are captured in this table

# The 400GbE Basic Layer Diagram



- But...
  - To enable flexibility for future efforts, an extender sublayer for the CDMII is desirable, but there is no physical instantiation of the CDMII.
  - From a standardization perspective, it can leverage a CDAUI, which is an optional physical instantiation of the PMA service interface

# PCS Block Diagrams



- Specific FEC code is TBD
- From gustlin\_3bs\_02\_0115

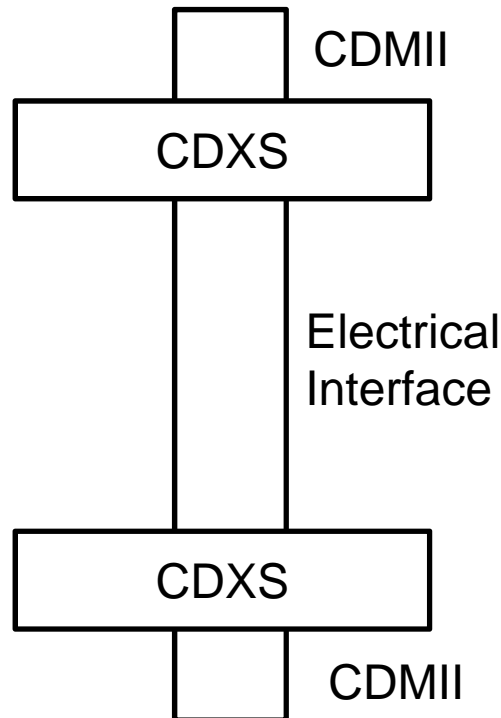


# PMA

The following are the functions performed by the PMA sublayer

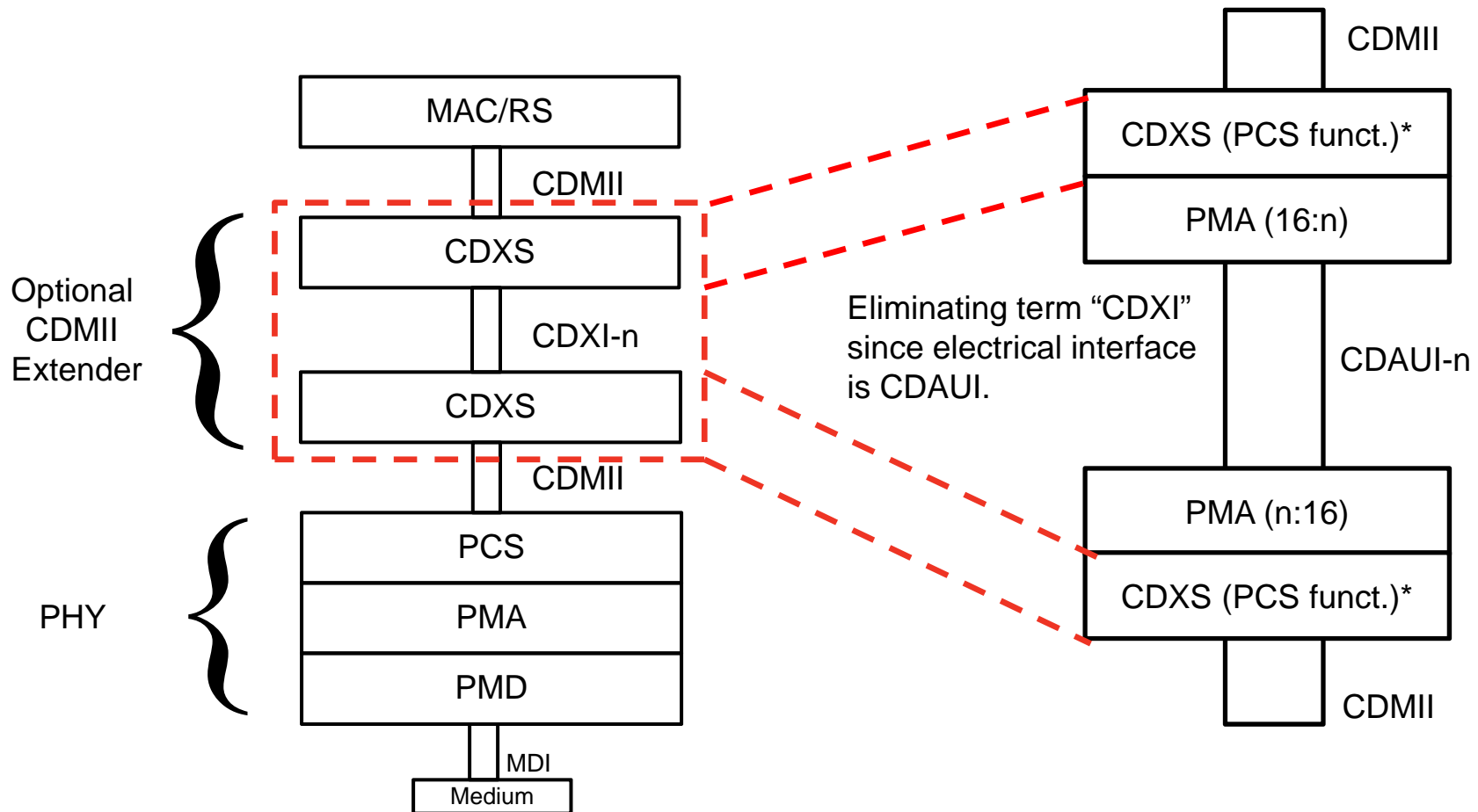
- Provide appropriate multiplexing
  - Provide appropriate modulation (PAM4 for instance if required)
  - Provide per input-lane clock and data recovery
  - Provide clock generation
  - Provide signal drivers
  - Optionally provide local loopback to/from the PMA service interface
  - Optionally provide remote loopback to/from the PMD service interface
  - Optionally provide test-pattern generation and detection
  - Tolerate Skew Variation
- 
- From gustlin\_3bs\_02\_0115

# Comments on CDXS



- CDMII is the only media independent interface
- Different implementations or future PHYs may require changing FEC, which would require a return to CDMII (from a standardization perspective)
- The CDXS, as shown, is an extension of the CDMII.
- This allows support for new PCS / PMA functionality below the extended CDMII, if needed.
- The CDXS provides the coding / FEC of the electrical interface, not the coding / FEC of the PHY.

# CDMII Extender Functional Concept

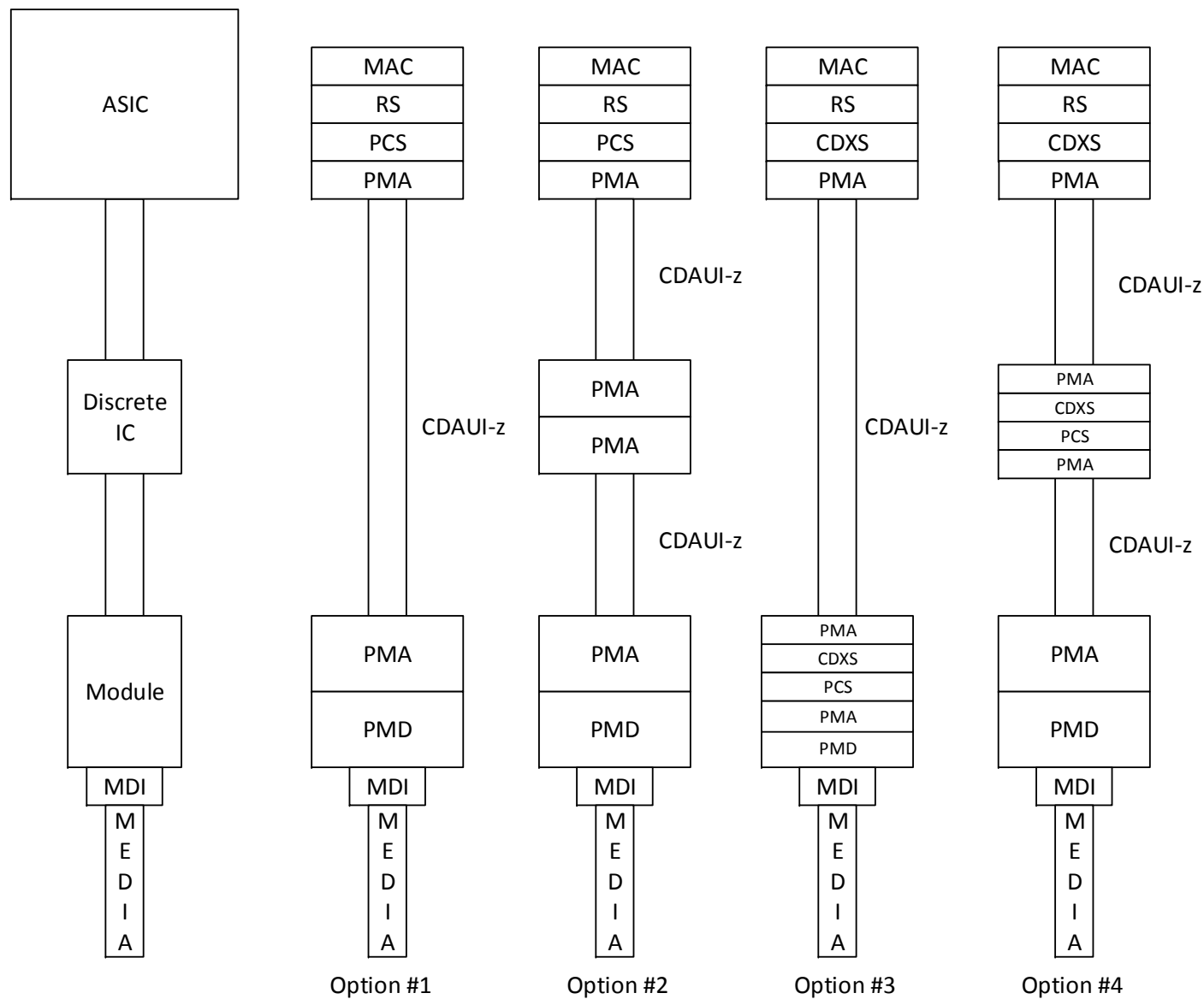


Initial Proposal

Updated Proposal

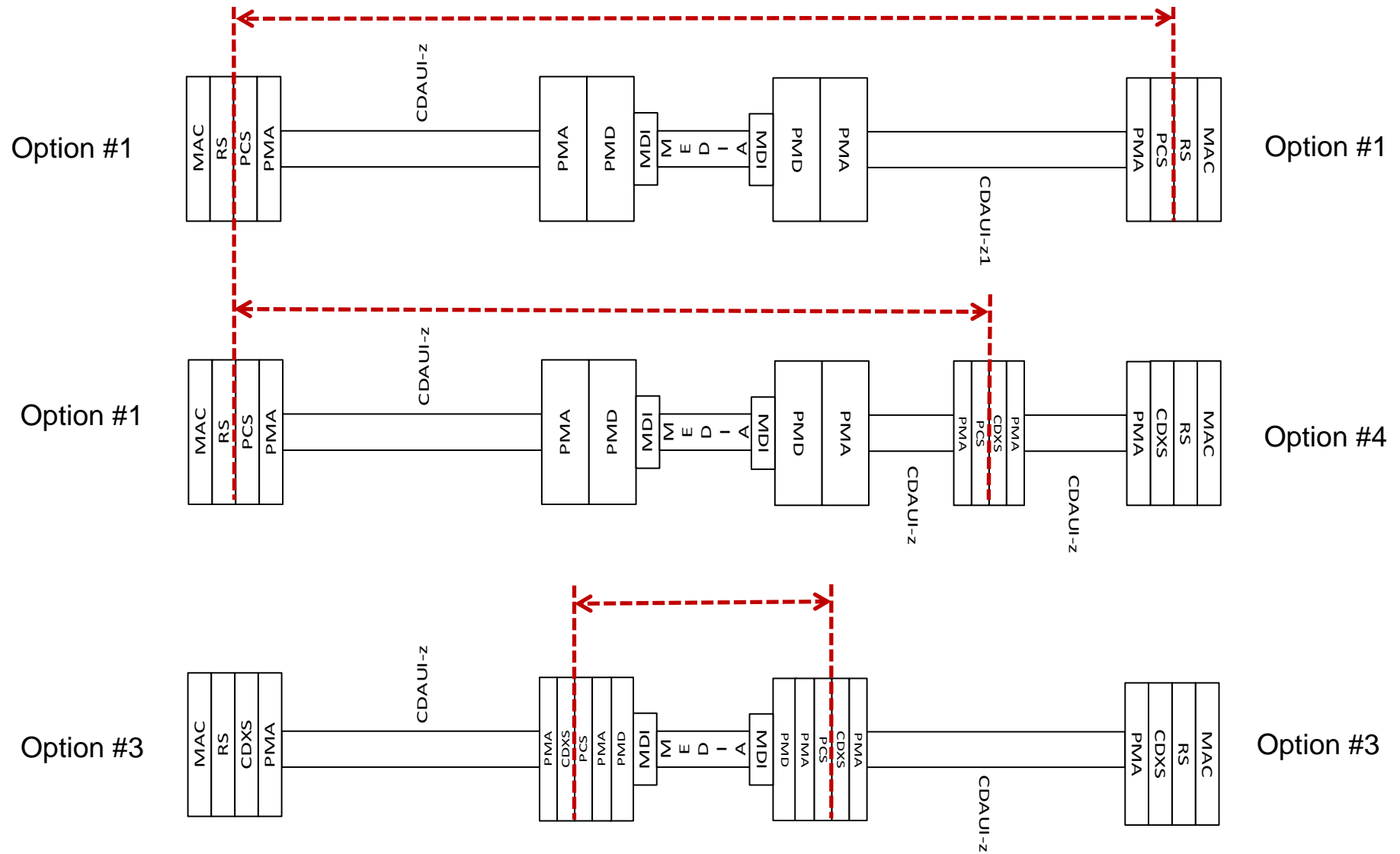
**\* Note - Same as PCS (including FEC) to be defined.**

# 400GbE Example Implementations



“z” may be different for various interfaces cited for CDAUI

# Leveraging the Proposed Architecture





# Thanks!

# 400GbE MII Baseline Proposal

**IEEE P802.3bs 400 Gb/s Ethernet Task Force**

July 2014 San Diego

Mark Gustlin – Xilinx

# Supporters

- John D'Ambrosia – Dell
- Arthur Marris – Cadence
- Dave Ofelt – Juniper
- Steve Trowbridge - ALU



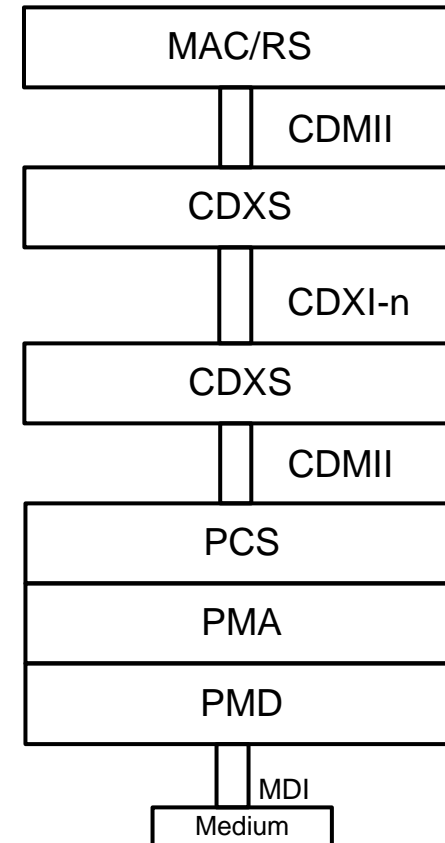
# Proposed 400GbE Architecture

- The protocol stack diagram shows one possible implementation
- The CDMII connects the MAC/RS sublayer to the Extender sublayer or the PCS

CDMII is the 400 Gb/s Media Independent Interface

CDXS is the 400 Gb/s extender sublayer

CDXI is the interface between two extender sublayers



# CDMII Interface

## ➤ Why define it?

- Electrically it won't be directly instantiated, but in the proposed 400GbE architecture it can be extended with an extender sublayer (CDXS) and interface (CDXI-n)
- Some will want it for RTL to RTL connections within devices

## ➤ Define it as a logical Interface only

- Unless it is extended, then there is a physical instantiation via an extender sublayer

# What is it?

- Base it directly on clause 81
- Same signal structure as shown below, just run faster, or in parallel

## 81.1.6 XLGMII/CGMII structure

The XLGMII/CGMII is composed of independent transmit and receive paths. Each direction uses 64 data signals (TXD<63:0> and RXD<63:0>), 8 control signals (TXC<7:0> and RXC<7:0>), and a clock (TX\_CLK and RX\_CLK). Figure 81–2 depicts a schematic view of the RS inputs and outputs.

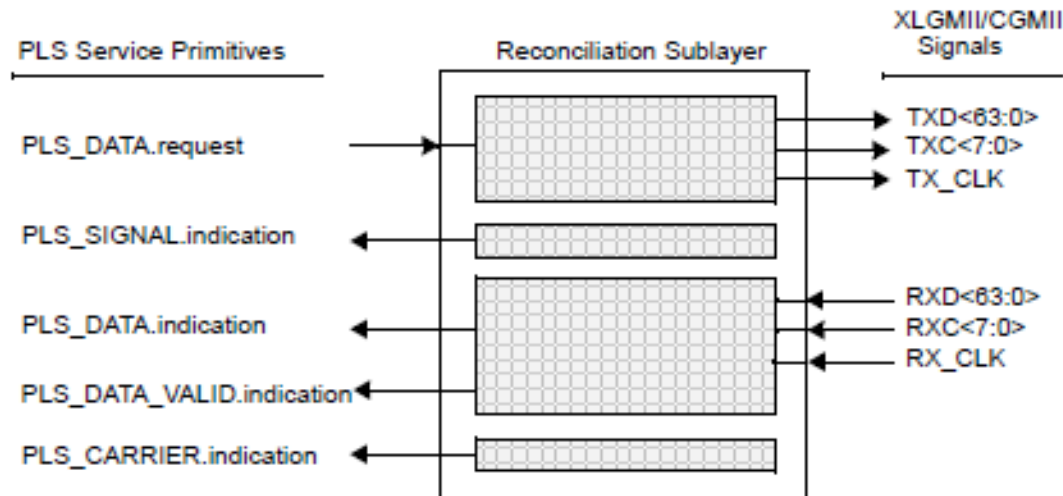


Figure 81–2—Reconciliation Sublayer (RS) inputs and outputs

# Extender Sublayer (CDXS)

- The CDXS is the proposed extender sublayer to extend the CDMII
  - A typical instantiation is a high speed parallel SerDes interface
- It is optional, only used if the PCS does not cover both the electrical and optical interface needs
- The CDXS can contain PCS, FEC, and PMA functionality

**Thanks!**

# **Baseline Proposal for CDAUI-8 Chip-to-Chip (c2c)**

For IEEE 802.3bs

Mike Peng Li, Altera  
Adam Healey, Avago Technologies  
Philip Fisher, Avago Technologies  
Cathy Liu, Avago Technologie  
Ed Frlan, Semtech  
David Brown, Semtech

# CDAUI-8 Baseline Proposal Supporters

## Contributors and Supporters

David Brown, Semtech  
Philip Fisher, Avago Technologies  
Ed Frlan, Semtech  
Adam Healey, Avago Technologies  
Mike Peng Li, Altera  
Cathy Liu, Avago Technologies

## Supporters

Thananya Baldwin, Ixia  
Vipul Bhatt, Inphi  
Sudeep Bhoja, InPhi  
Will Bliss, Broadcom  
Matt Brown, Applied Micro  
Wheling Cheng , Ericsson  
**Chris Cole, Finisar**  
**Ali Ghiasi, Ghiasi Quantum LLC**  
Sacha Corbeil, JDSU  
Ian Dedic, **Socionext Europe GmbH**  
John Ewen, IBM  
Mike Furlong, Clariphy  
Mark Gustlin, Xilinx  
Zhensheng Jia, ZTE  
Scott Kipp, Brocade  
Beth Kochuparambil, Cisco  
Martin Langhammer, Altera  
Ryan Latchman, MACOM  
Greg LeCheminant, Keysight  
David Lewis, JDSU  
Jon Lewis, Dell  
Kent Lusted, Intel  
Jeffery J. Maki, Juniper Networks  
Marco Mazzini, Cisco  
Richard Mellitz, Intel  
Gary Nicholl, Cisco

Mark Nowell, Cisco  
David Ofelt, Juniper Networks  
Andre Szczepanek , InPhi  
Jerry Pepper, Ixia  
**Rick Rabinovich, Alcatel-Lucent Enterprise**  
Adee Ran, Intel  
Vineet Salunke, Cisco  
Kapil Shrikhande, Dell  
Jeff Slavick, Avago Technologies  
Bharat Tailor, Semtech  
Vivek Telang, Broadcom  
Alan Tipper, Semtech  
Pirooz Tooyserkani, Cisco  
Francois Tremblay, Semtech  
Michael Vitic, JDSU  
Xinyuan Wang, Huawei  
David Warren, HP Networking  
Brian Welch, Luxtera  
Helen Xu, Huawei  
Pavel Zivny, Tektronix

\* Changes since *li\_3bs\_01\_0115*  
shown in red

# Purposes

- Present a PAM4 baseline specification proposal for CDAUI-8 c2c electrical interface in support of the 400 GbE to fulfill its objective of:

Support optional 400 Gb/s Attachment Unit Interfaces for chip-to-chip and chip-to-module applications



# Technology Choice Highlights 1

- Channel target/requirement based on the equation of the following:

$$- IL \leq \{ 1.083 + 2.543\text{SQROOT}(f) + 0.761f \quad 0.01 \leq f \leq 28.05\text{GHz} \} \text{ dB}$$

as the informative insertion loss equation adopted by 802.3bs in Jan/2015 meeting

- Channel equalization based on a transceiver having TX FIR, RX CTLE and DFE

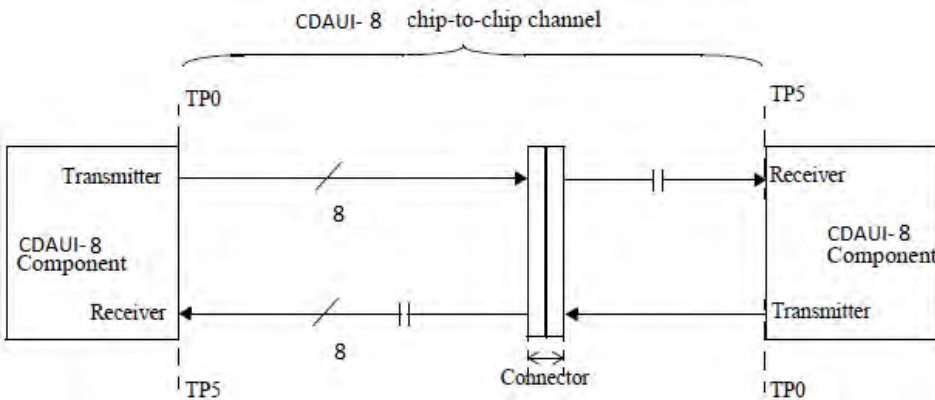
# Technology Choice Highlights 2

- Raw BER of CDAUI-8 link to be  $< 1\text{E-}6$ ; FEC brings link system BER to  $< 1\text{E-}15$

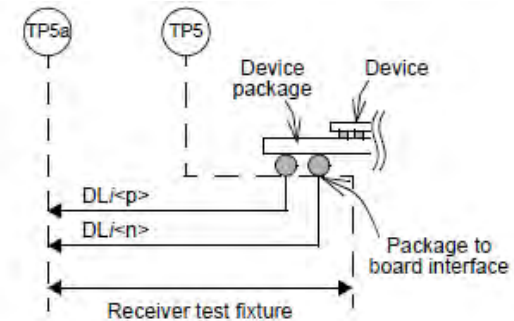
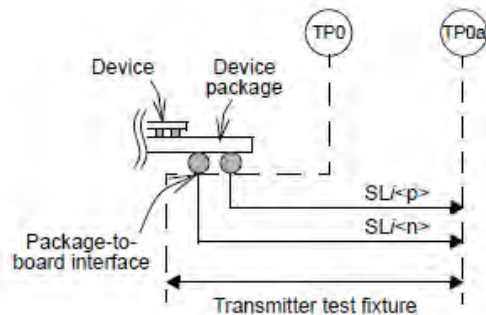
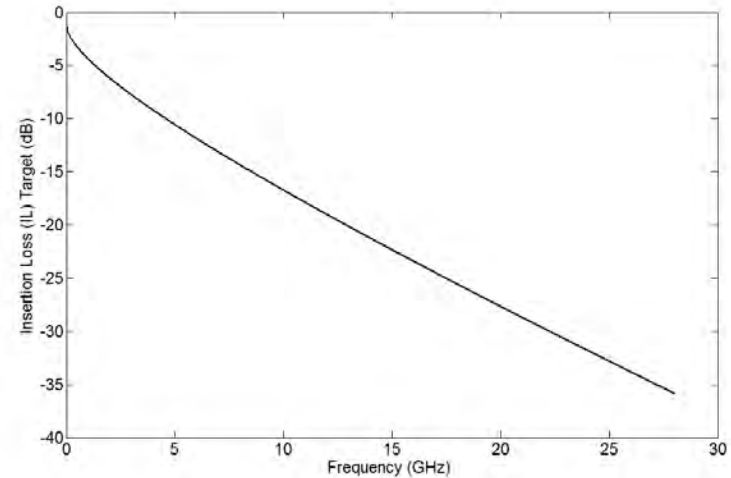
# Technology Choice Highlights 3

- Leverage the 100GBASE-KP4 (i.e., KP4) specification from 13.59 GBd to **26.5625** GBd, and is consistent with CEI-56G-MR specification draft<sup>[1]</sup>
- Gray-code proposed, FEC (capable of bringing raw BER from  $1e-6$  to  $< 1e-15$  ) assumed. FEC and pre-coding (if needed) specifics be defined by the FEC ad hoc
- Reuse KP4 test patterns, TX and RX methodologies for specifying electrical characteristics and corresponding tests
- Reuse CAUI-4 TX and RX diff and CM RLs, compliance point definitions (i.e., TP0a and TP5a)
- Reuse CAUI-4 link adaptation method (i.e., CL 83D.3.3.2 and 45)
- Reuse/**improve** 802.3bj COM method channel compliance with PAM4 signaling

# CDAUI-8 c2c Link Topology and IL Target



Informative target Max IL



- CDAUI-8 c2c compliance point definitions are the same as those defined in clause 83D.2 (CAUI-4)

# CDAUI-8 c2c Functional Spec

- CDAUI-8 PMA functional spec will be largely base on reusing, extending/modifying Clauses 94.2.2 (TX), 94.2.3 (RX), including
  - FEC interface
    - KP4 FEC, i.e., RS(544, 514, 10)
  - Gray mapping
  - PAM4 encoding
  - Precoding
    - Pending, the need and specifics ought to be studied and determined in the FEC ad hoc

# CDAUI-8 c2c Test Patterns

- CDAUI-8 PMA will reuse test patterns defined in clause 94.2.9, including:
  - JP03A test pattern
  - JP03B test pattern
  - Quaternary PRBS13 test pattern (**with the termination block (i.e., 94.2.2.4) removed**, this will need to be changed accordingly)
  - Transmitter linearity test pattern

# CDAUI-8 c2c TX Spec

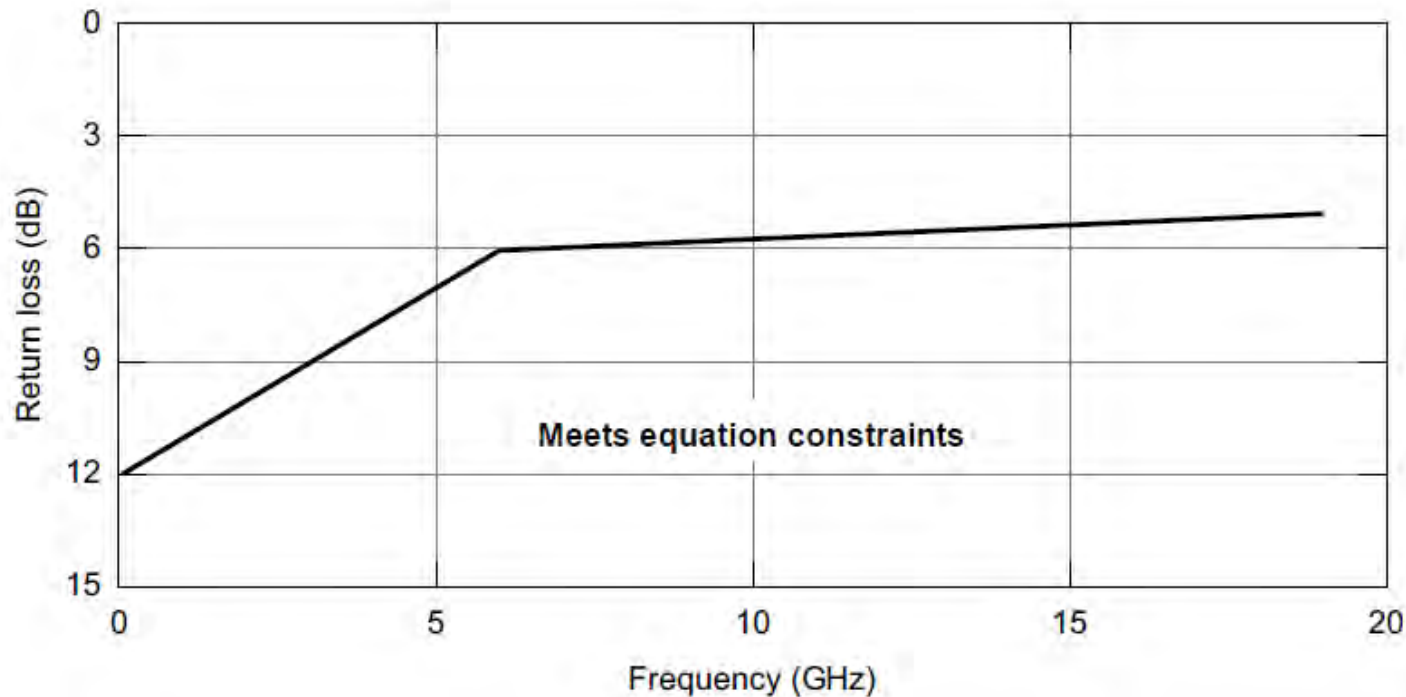
Parameter	Subclause reference	Value	Units
Signaling rate		26.5625	Gsym/s
Differential peak-to-peak output voltage (max.) Transmitter disabled Transmitter enabled		30 1200	mV mV
DC common-mode output voltage (max.)		1.9	V
DC common-mode output voltage (min.)		0	V
AC common-mode output voltage (RMS, max.)		30	mV
Differential output return loss (min.)		Eq. 17-4	dB
Common-mode output return loss (min.)		Eq. 17-5	dB
Output waveform Level separation mismatch ratio, RLM (min.) Steady-state voltage $V_f$ (max.) Steady-state voltage $V_f$ (min.) Linear fit pulse peak (min.) Normalized coefficient step size (min.) Normalized coefficient step size (max.) Pre-cursor full-scale range (min.) Post-cursor full-scale range (min.)		0.92 0.6 0.4 $0.80 \times V_f$ 0.0083 0.05 1.54 4	— V V V — — — —
Output jitter and linearity Clock random jitter, RMS (max.) Clock deterministic jitter, pp (max.) Even-odd jitter (max.) Signal-to-noise-and-distortion ratio (min.)		0.01 0.04 0.019 31	UI UI UI dB

- TX output waveform definition and test method will reuse clause 94.3.12.5
- TX output jitter definition and test method will reuse clause 94.3.12.6
- TX output noise and distortion definition and test method will reuse clause 94.3.12.7

\* Updated to be aligned/consistent with healey\_3bs\_01\_0315

# CDAUI-8 c2c TX Diff RL Spec

$$RL_d(f) \geq \left\{ \begin{array}{ll} 12.05 - f & 0.05 \leq f \leq 6 \\ 6.5 - 0.075f & 6 < f \leq 19 \end{array} \right\} \text{ dB}$$

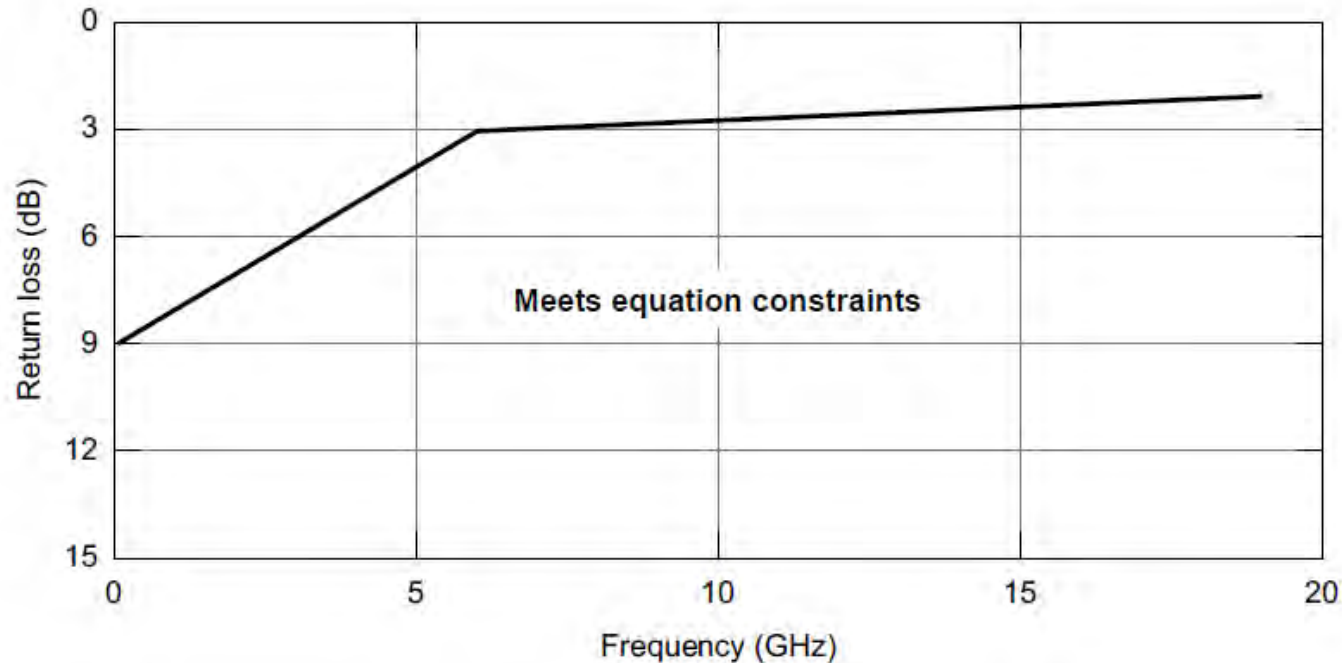


- Reuse Eq. (93-3) and Fig (93-7)



# CDAUI-8 c2c TX CM RL Spec

$$RL_{cm}(f) \geq \begin{cases} 9.05 - f & 0.05 \leq f \leq 6 \\ 3.5 - 0.075f & 6 < f \leq 19 \end{cases} \text{ dB}$$



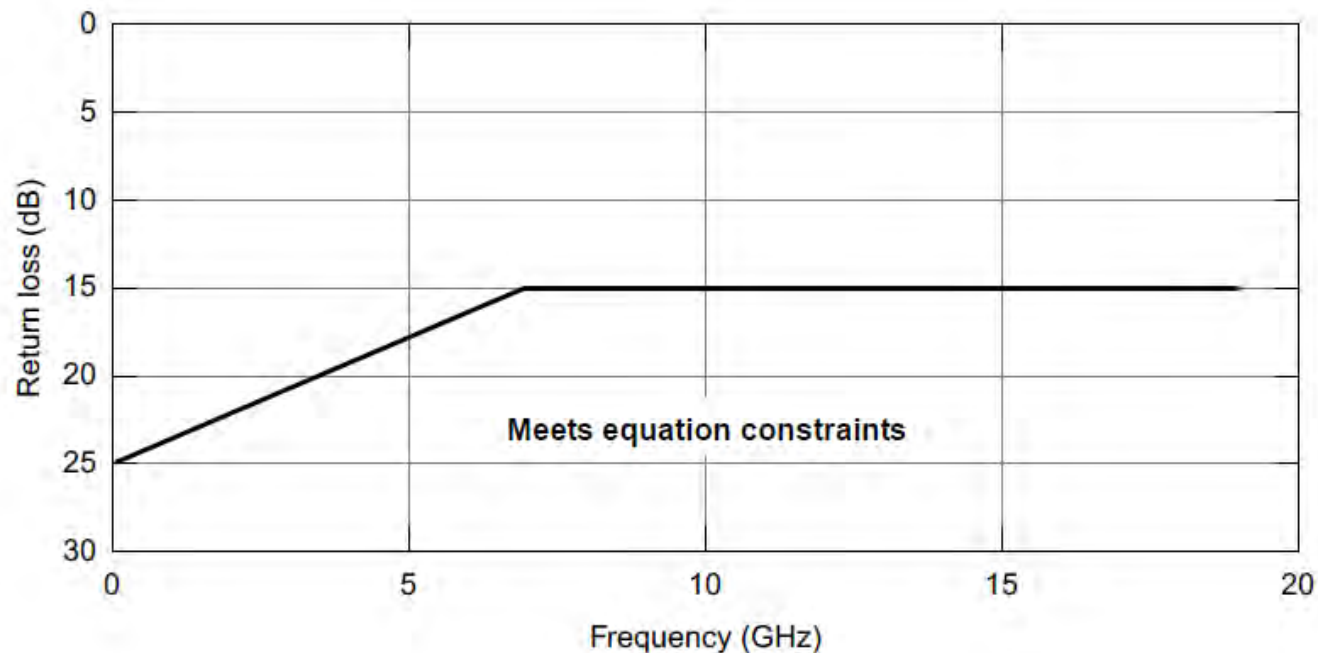
- Reuse Eq. (93-4) and Fig (93-8)

# CDAUI-8 c2c RX Spec

Parameter	Symbol	Value	Units	Conditions
Differential Input Return Loss		Slide 11	dB	
Differential to Common-Mode Return Loss		Slide 14	dB	
Interference Tolerance		Slide 15	-	
Jitter Tolerance		Slide 16	-	

# CDAUI-8 c2c RX D2C RL Spec

$$RL_{cd}(f) = \left\{ \begin{array}{ll} 25 - 1.44f & 0.05 \leq f \leq 6.95 \\ 15 & 6.95 < f \leq 19 \end{array} \right\} \text{ dB}$$



- Reuse Eq. (93-5) and Fig (93-11)

# CDAUI-8 c2c RX Interference Tolerance Parameters

Parameter	Test 1 values			Test 2 values			Units
	Min	Max	Target	Min	Max	Target	
Symbol error ratio <sup>a</sup>	—	$10^{-5}$		—	$10^{-5}$		—
Insertion loss at 13.2813 GHz <sup>b</sup>	19.5	20.5		9.5	10.5		dB
Coefficients of fitted insertion loss <sup>c</sup>							
a0	-1	2		-1	1		dB
a1	0	2.937		0	0.817		dB/GHz <sup>1/2</sup>
a2	0	1.599		0	0.801		dB/GHz
a4	0	0.03		0	0.01		dB/GHz <sup>2</sup>
RSS_DFE4 <sup>d</sup>	0.05	—		0.025	—		—
COM including effects of broad-band noise	—	—	2	—	—	2	dB

<sup>a</sup> The FEC symbol error ratio is measured in step 11 of the receiver interference tolerance method defined in 93C.2

<sup>b</sup> Measured between TPt and TP5 (see Figure 93C-4)

<sup>c</sup> Coefficients are calculated from the insertion loss measured between TPt and TP5 (see Figure 93C-4) using the method in 93A.3 with  $f_{min} = 0.05$  GHz, and  $f_{max} = 26.5625$  GHz, and maximum  $\Delta f = 0.01$  GHz

<sup>d</sup> RSS\_DFE4 is described in 93A.2.

- Largely re-use of Table 83D-5 and method in 94.3.13.3

# CDAUI-8 c2c RX Jitter Tolerance Parameters

Parameter	Case A values	Case B values	Units
Max Pre-FEC BER	1e-6	1e-6	
Jitter frequency	$fb/849600$	$fb/8496$	same as $fb$
Jitter Amplitude	5	0.05	UI

- Largely re-use method in 94.3.13.4
- $fb$  is the BAUD rate

# CDAUI-8 c2c Channel Spec: COM (I)\*

Parameter	Symbol	Value	Units
Signaling rate	$f_b$	26.5625	GBd
Maximum start frequency	$f_{min}$	0.05	GHz
Maximum frequency step	$\Delta f$	0.01	GHz
Device package model Single-ended device capacitance Transmission line length, Test 1 Transmission line length, Test 2 Single-ended package capacitance at package-to-board interface	$C_d$ $Z_p$ $Z_p$ $C_p$	TBD 12 30 TBD	nF mm mm nF
Single-ended reference resistance	$R_0$	50	$\Omega$
Single-ended termination resistance	$R_d$	TBD	$\Omega$
Receiver 3 dB bandwidth	$f_r$	$0.75 \times f_b$	
Transmitter equalizer, minimum cursor coefficient	$c(0)$	0.60	—
Transmitter equalizer, pre-cursor coefficient Minimum value Maximum value Step size	$c(-1)$	— -0.15 0 0.05	— — — —
Transmitter equalizer, post-cursor coefficient Minimum value Maximum value Step size	$c(1)$	— -0.25 0 0.05	— — — —
Continuous time filter, DC gain Minimum value Maximum value Step size	$g_{DC}$	-15 0 1	dB dB dB
Continuous time filter, zero frequency	$f_z$	$f_b / 4$	GHz
Continuous time filter, pole frequencies	$f_{p1}$ $f_{p2}$	$f_b / 4$ $f_b$	GHz
Transmitter differential peak output voltage Victim Far-end aggressor Near-end aggressor	$A_v$ $A_{fe}$ $A_{ne}$	0.4 0.4 0.6	V V V

\* Updated to be aligned/consistent with healey\_3bs\_01\_0315

# CDAUI-8 c2c Channel Spec: COM (II)

Number of signal levels	$L$	4	—
Level separation mismatch ratio	$R_{LM}$	0.92	—
Transmitter signal-to-noise ratio	$SNR_{TX}$	31	dB
Number of samples per unit interval	$M$	32	—
Decision feedback equalizer (DFE) length	$N_b$	5	UI
Normalized DFE coefficient magnitude limit for $n = 1$ for $n = 2$ to $N_b$	$b_{max}(n)$	1 0.2	—
Random jitter, RMS	$\sigma_{RJ}$	0.01	UI
Dual-Dirac jitter, peak	$A_{DD}$	0.02	UI
One-sided noise spectral density	$\eta_0$	$5.2 \times 10^{-8}$	V <sup>2</sup> /GHz
Target detector error ratio	$DER_0$	$10^{-6}$	—

\* Updated to be aligned/consistent with *healey\_3bs\_01\_0315*

# Summary

- A baseline proposal based PAM4 signaling for CDAUI-8 c2c electrical interface specification has been developed
  - Intent is to support existing CAUI-4 c2c channel and testing infrastructures
  - Reused/extended/modified from 100GBase-KP4 and CAUI-4 c2c specifications (i.e., clauses 94, 93A, and 83D)
  - Consistent with CEI-56G-MR adopted baseline specification in modulation and in general



# References

[1] oif2014.245.01, [www.oiforum.com](http://www.oiforum.com)

(That document was provided as an attachment to the October 28, 2014 liaison from OIF to IEEE 802.3. The liaison and its attachments can be found in the IEEE P802.3bs 400 Gb/s Ethernet Task Force private area)

# **Baseline Proposal for CDAUI-8 Chip-to-Module (c2m)**

For IEEE 802.3bs

Mike Peng Li, Altera  
Adam Healey, Avago Technologies  
Philip Fisher, Avago Technologies  
Cathy Liu, Avago Technologies  
Ed Frlan, Semtech  
David Brown, Semtech

# CDAUI-8 c2m Baseline Document Supporters

\*

## Contributors and Supporters

- David Brown, Semtech
- Philip Fisher, Avago Technologies
- Ed Frlan, Semtech
- Adam Healey, Avago Technologies
- Mike Peng Li, Altera
- Cathy Liu, Avago Technologies

## Supporters

Thananya Baldwin, Ixia  
Vipul Bhatt, Inphi  
Sudeep Bhoja, InPhi  
Will Bliss, Broadcom  
Matt Brown, Applied Micro  
Wheling Cheng, Ericsson  
Chris Cole, Finisar  
Sacha Corbeil, JDSU  
Ian Dedic, Socionext Europe  
John Ewen, IBM  
Mike Furlong, Clariphy  
Ali Ghiasi, Ghiasi Quantum LLC  
Mark Gustlin, Xilinx  
Zhensheng Jia, ZTE  
Scott Kipp, Brocade  
Beth Kochuparambil, Cisco  
Martin Langhammer, Altera  
Ryan Latchman, MACOM  
Greg Le Cheminant, Keysight  
David Lewis, JDSU  
Jon Lewis, Dell  
Kent Lusted, Intel  
Jeffery J. Maki, Juniper Networks  
Marco Mazzini, Cisco  
Richard Mellitz, Intel

Gary Nicholl, Cisco  
Mark Nowell, Cisco  
David Ofelt, Juniper  
Jerry Pepper, Ixia  
Rick Rabinovich, Alcatel-Lucent Enterprise  
Adee Ran, Intel  
Vineet Salunke, Cisco  
Kapil Shrikhande, Dell  
Jeff Slavick, Avago Technologies  
Andre Szczepanek, InPhi  
Bharat Tailor, Semtech  
Vivek Telang, Broadcom  
Alan Tipper, Semtech  
Pirooz Tooyserkani, Cisco  
Francois Tremblay, Semtech  
Michael Vitic, JDSU  
Xinyuan Wang, Huawei  
David Warren, HP Networking  
Brian Welch, Luxtera  
Helen Xu, Huawei  
Pavel Zivny, Tektronix

\* Changes since  
*brown\_3bs\_01a\_0115* shown in red

# Purpose

- Present a baseline specification proposal for CDAUI-8 c2m electrical interface in support of the 400 GbE Task Force to fulfill its objective of:

Support optional 400 Gb/s Attachment Unit Interfaces for chip-to-chip and chip-to-module applications

# Technology Choice Highlights 1

- Channel target/requirement based on the following equation:

$$IL \leq \{ 1.076(0.075 + 0.537\text{SQROOT}(f) + 0.566f) \quad 0.01 \leq f \leq 28.05\text{GHz} \} \text{ dB}$$

as the informative insertion loss adopted by 802.3bs at the Jan/2015 Interim meeting

- Channel equalization based on a transceiver having autonomous Rx CTLE
  - Tx FIR or Rx DFE not specified in host or module transceivers. (Allowed, but not mandated.)

# Technology Choice Highlights 2

- Raw BER of CDAUI-8 c2m link to be  $< 1e-6$ ; FEC brings link system BER to  $< 1e-15$

# Technology Choice Highlights 3

\*

- Leverage the CEI-56G-VSR-PAM4 draft specification<sup>[1]</sup> using **one** data rate:
  - 26.5625GBd
- Gray-code specified, FEC assumed but not specified
- Pre-coding not assumed since CTLE-only
- Reuse CAUI-4 c2m Tx and Rx methodologies for specifying electrical characteristics and corresponding tests
  - Diff and CM RLs and compliance point definitions
  - HCB/MCB method for channel compliance, adapted for PAM-4 signaling
  - Remove “recommended CTLE” mechanism

# CDAUI-8 Chip-to-Module Link

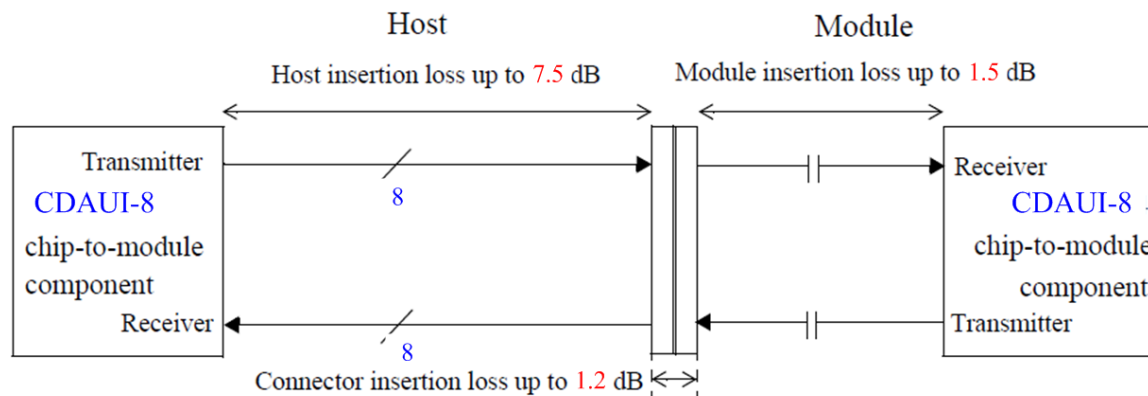
\*

	CAUI-4 (83E.3.1 TP1a)	VSR 56G (15.3.2, TP1a)	CDAUI-8 Chip-Module Potential
Modulation	NRZ	PAM-4 (Gray coded)	PAM-4 (Gray coded)
Nominal Signaling Rate (each lane)	25.78125 Gb/s +/- 100 ppm	$19.6 \leq f_b \leq 30$ GBd	26.5625 GBd +/- 100 ppm <del>28 GBd (TBD)<sup>a</sup> +/- 100 ppm</del>
Unit Interval	38.787879 ps	33.33 ps - 51 ps	37.647059 ps <del>35.65 ps (TBD)<sup>a</sup></del>
Loss Budget, max <sup>b</sup>	10 dB	10.8 dB <sup>c</sup>	10.3 dB
Uncorrected BER	< 1e-15	< 1e-6	< 1e-6
Corrected BER	n/a	n/a	< 1e-15

<sup>a</sup> ~~Two operating signaling rates, with choice of higher rate pending PMA FEC selection.~~

<sup>b</sup> At 1/2 symbol rate, comprising host PCB trace, module PCB trace, AC-coupling capacitors and one connector.

<sup>c</sup> Informative.

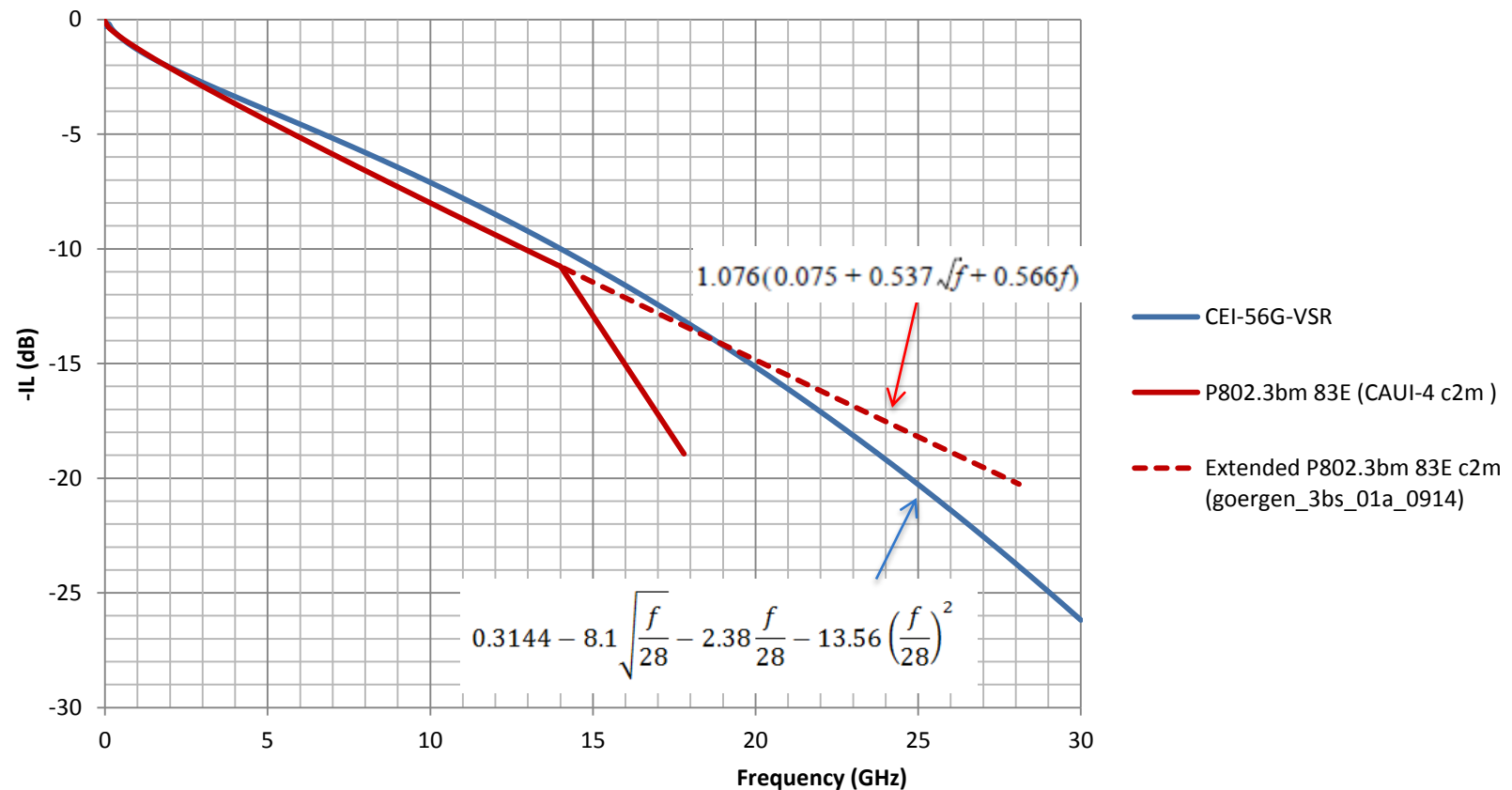


Chip-to-module insertion loss budget at 13.28 GHz



# CDAUI-8 c2m PAM4 Channel Insertion Loss

\*



- Target IL curve is “extended CAUI-4 c2m” as adopted at Jan/2015 Interim
  - Loss at Nyquist (13.28GHz) = 10.27 dB
  - Working assumption: all IL curves shown are suitable for PAM4 signaling at 28Gb/s
  - Consider potential to operate over legacy CAUI-4 c2m channels

# CDAUI-8 Host Transmitter

	CAUI-4 (83E.3.1 TP1a)	VSR 56G (15.3.2, TP1a)	CDAUI-8 Chip-Module Potential
Differential peak-to-peak output voltage (max) with Tx enabled	900 mV	900 mV	900 mV
AC common-mode output voltage (max)	17.5 mVrms	17.5 mVrms	17.5 mVrms
Differential peak-to-peak output voltage (max) with Tx disabled	35 mV	-	35 mV
Differential termination mismatch (max)	10 %	10 %	10 %
Differential output return loss (min)	$\geq 9.5-0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75-7.4\log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz	$\geq 11$ , $0.05 \leq f \leq f_b/7$ GHz $\geq 6-9.2\log_{10}(2f/f_b)$ , $f_b/7 \leq f \leq f_b$ GHz	$\geq 9.5-0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75-7.4\log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz
Common-mode to differential output return loss (min)	$\geq 22-(20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15-(6/25.78)f$ , $12.89 \leq f \leq 19$ GHz	$\geq 22-14f/f_b$ , $0.05 \leq f \leq f_b/2$ GHz $\geq 18-6f/f_b$ , $f_b/2 \leq f \leq f_b$ GHz	$\geq 22-(20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15-(6/25.78)f$ , $12.89 \leq f \leq 19$ GHz
Common-mode output return loss (min)	-	2 dB	2 dB
DC common-mode output voltage (max)	2.8 V	2.8 V	2.8 V
DC common-mode output voltage (min)	-0.3 V	-0.3 V	-0.3 V
Eye Width (min)	0.46 UI at 1e-15	0.25 UI at 1e-6 applicable to all three PAM4 eyes	0.25 UI at 1e-6 applicable to all three PAM4 eyes
Output total jitter (max)	TJ: 0.54UIpp @ 1e-15 Measured using CTLE	TJ: 0.75UIpp @ 1e-6 Measured using CTLE	TJ: 0.75UIpp @ 1e-6 Measured using CTLE
Eye Height (min)	95 mV at 1e-15	50 mV at 1e-6 applicable to all three PAM4 eyes	50 mV at 1e-6 applicable to all three PAM4 eyes
Transition time (min, 20/80%)	10 ps	-	-

# CDAUI-8 Module Receiver

	CAUI-4 (83E.3.1 TP1)	VSR 56G (15.3.2, TP1)	CDAUI-8 Chip-Module Potential
Differential peak-to-peak input voltage tolerance (min)	900 mV	900 mV	900 mV
Single-ended voltage tolerance range (min)	-0.4 to 3.3 V	-	-
DC common-mode input voltage (max)	2.85 V	2.85 V	2.85 V
DC common-mode input voltage (min)	-0.35 V	-0.35 V	-0.35 V
Differential termination mismatch (max)	10 %	10 %	10 %
Differential input return loss (min)	$\geq 9.5-0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75-7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz	$\geq 11$ , $0.05 \leq f \leq f_b/7$ GHz $\geq 6-9.2 \log_{10}(2f/f_b)$ , $f_b/7 \leq f \leq f_b$ GHz	$\geq 9.5-0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75-7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz
Differential to common mode input return loss (min)	$\geq 22-(20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15-(6/25.78)f$ , $12.89 \leq f \leq 19$ GHz	$\geq 22-14f/f_b$ , $0.05 \leq f \leq f_b/2$ GHz $\geq 18-6f/f_b$ , $f_b/2 \leq f \leq f_b$ GHz	$\geq 22-(20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15-(6/25.78)f$ , $12.89 \leq f \leq 19$ GHz
Module stressed input test	83E.3.4.1	15.3.10.2.1	Same as VSR

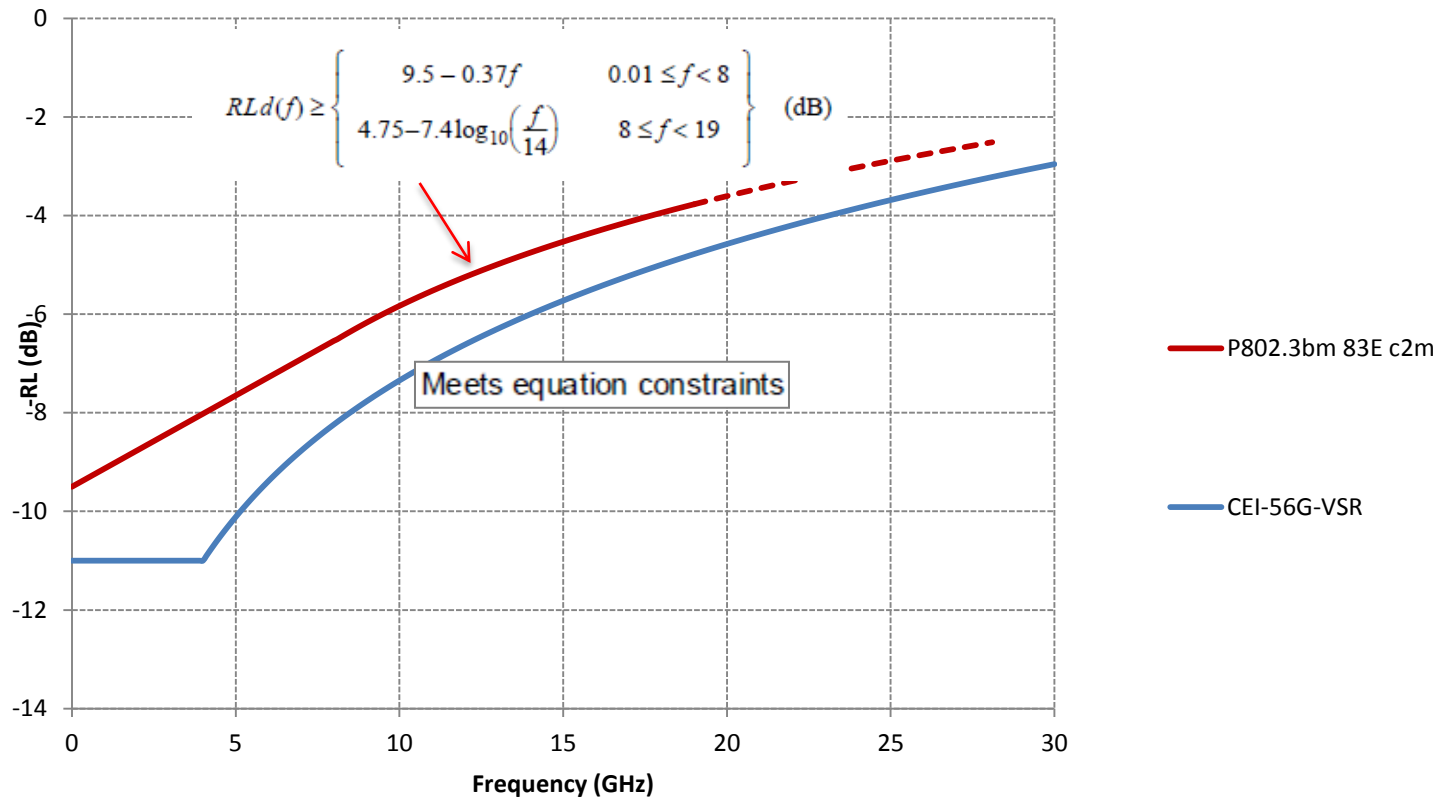
# CDAUI-8 Module Transmitter

	CAUI-4 (83E.3.2 TP4)	VSR 56G (15.3.3, TP4)	CDAUI-8 Chip-Module Potential
Differential peak-to-peak output voltage (max) with Tx enabled	900 mV	900 mV	900 mV
AC common-mode output voltage (max)	17.5 mVrms	17.5 mVrms	17.5 mVrms
Differential termination mismatch (max)	10 %	10 %	10 %
Differential output return loss (min)	$\geq 9.5 - 0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75 - 7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz	$\geq 11$ , $0.05 \leq f \leq f_b/7$ GHz $\geq 6 - 9.2 \log_{10}(2f/f_b)$ , $f_b/7 \leq f \leq f_b$ GHz	$\geq 9.5 - 0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75 - 7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz
Common-mode to differential mode output return loss (min)	$\geq 22 - (20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15 - (6/25.78)f$ , $12.89 \leq f \leq 19$ GHz	$\geq 22 - 14f/f_b$ , $0.05 \leq f \leq f_b/2$ GHz $\geq 18 - 6f/f_b$ , $f_b/2 \leq f \leq f_b$ GHz	$\geq 22 - (20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15 - (6/25.78)f$ , $12.89 \leq f \leq 19$ GHz
Common-mode output return loss (min)	-	2 dB	2 dB
DC common-mode output voltage (max)	2.85 V	2.85 V	2.85 V
DC common-mode output voltage (min)	-0.35 V	-0.35 V	-0.35 V
Vertical Eye Closure (max)	5.5 dB	5.8 dB	5.8dB
Eye Width (min)	0.57 UI at 1e-15	0.4 UI at 1e-6 applicable to all three PAM4 eyes	0.4 UI at 1e-6 applicable to all three PAM4 eyes
Output total jitter (max)	TJ: 0.43UIpp @ 1e-15 Measured using CTLE	TJ: 0.6UIpp @ 1e-6 Measured using CTLE	TJ: 0.6UIpp @ 1e-6 Measured using CTLE
Eye Height (min)	228 mV at 1e-15	120 mV at 1e-6 applicable to all three PAM4 eyes	120 mV at 1e-6 applicable to all three PAM4 eyes
Transition time (min, 20/80%)	12 ps	-	-

# CDAUI-8 Host Receiver

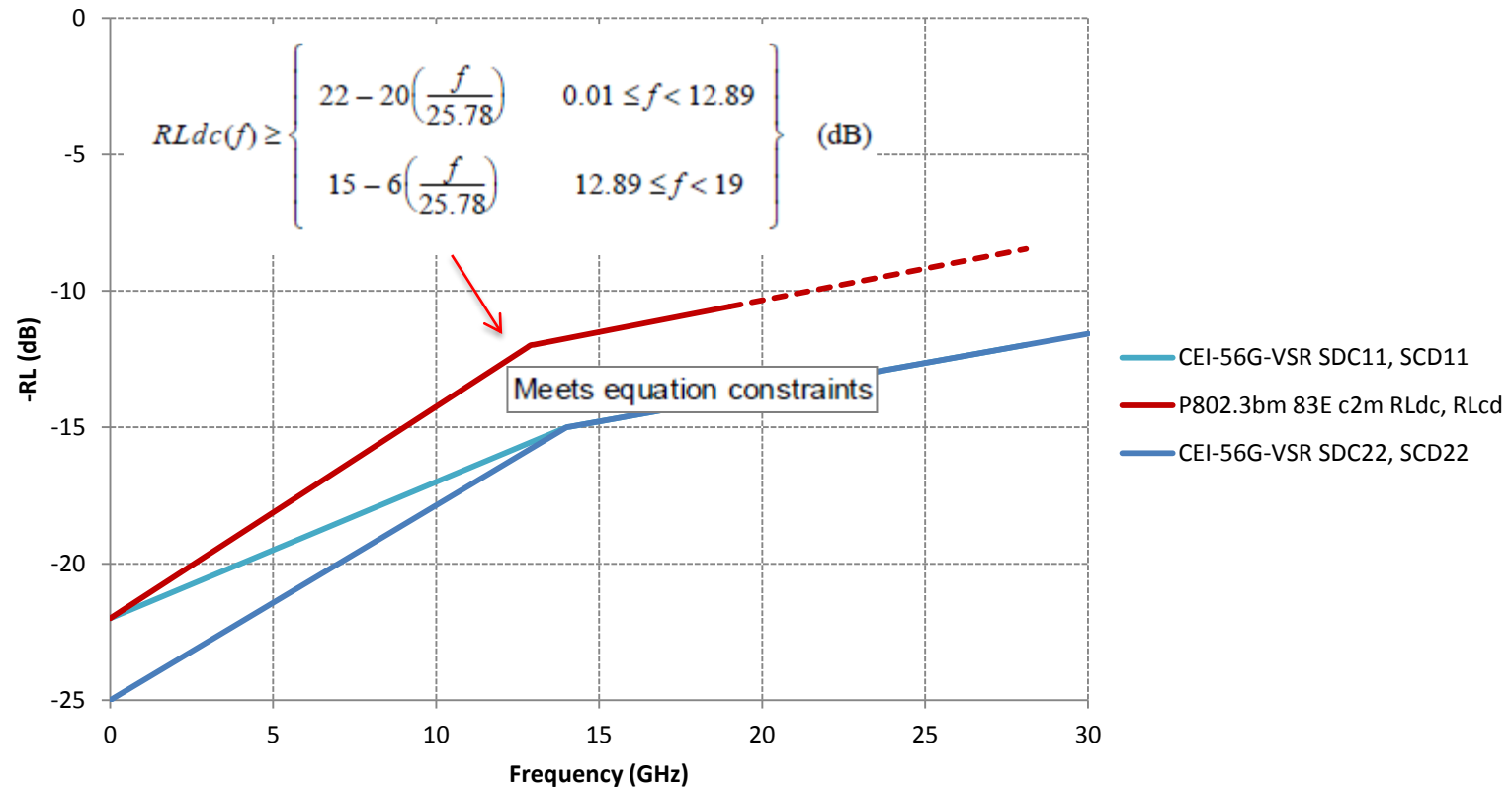
	CAUI-4 (83E.3.2 TP4a)	VSR 56G (15.3.2, TP4a)	CDAUI-8 Chip-Module Potential
Differential peak-to-peak input voltage tolerance (min)	900 mV	900 mV	900 mV
DC common-mode input voltage (max)	2.8 V	2.8 V	2.8 V
DC common-mode input voltage (min)	-0.3 V	-0.3 V	-0.3 V
Differential termination mismatch (max)	10 %	10 %	10 %
Differential input return loss (min)	$\geq 9.5 - 0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75 - 7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz	$\geq 11$ , $0.05 \leq f \leq f_b/7$ GHz $\geq 6 - 9.2 \log_{10}(2f/f_b)$ , $f_b/7 \leq f \leq f_b$ GHz	$\geq 9.5 - 0.37f$ , $0.01 \leq f \leq 8$ GHz $\geq 4.75 - 7.4 \log_{10}(f/14)$ , $8 \leq f \leq 19$ GHz
Differential to common-mode input return loss (min)	$\geq 22 - (20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15 - (6/25.78)f$ , $12.89 \leq f \leq 19$ GHz	$\geq 22 - 14f/f_b$ , $0.05 \leq f \leq f_b/2$ GHz $\geq 18 - 6f/f_b$ , $f_b/2 \leq f \leq f_b$ GHz	$\geq 22 - (20/25.78)f$ , $0.01 \leq f \leq 12.89$ GHz $\geq 15 - (6/25.78)f$ , $12.89 \leq f \leq 19$ GHz
Host stressed input test	83E.3.3.2	15.3.10.2.1	Same as VSR
Jitter tolerance	-	-	-

# CDAUI-8 c2m Tx & Rx Differential Return Loss Spec



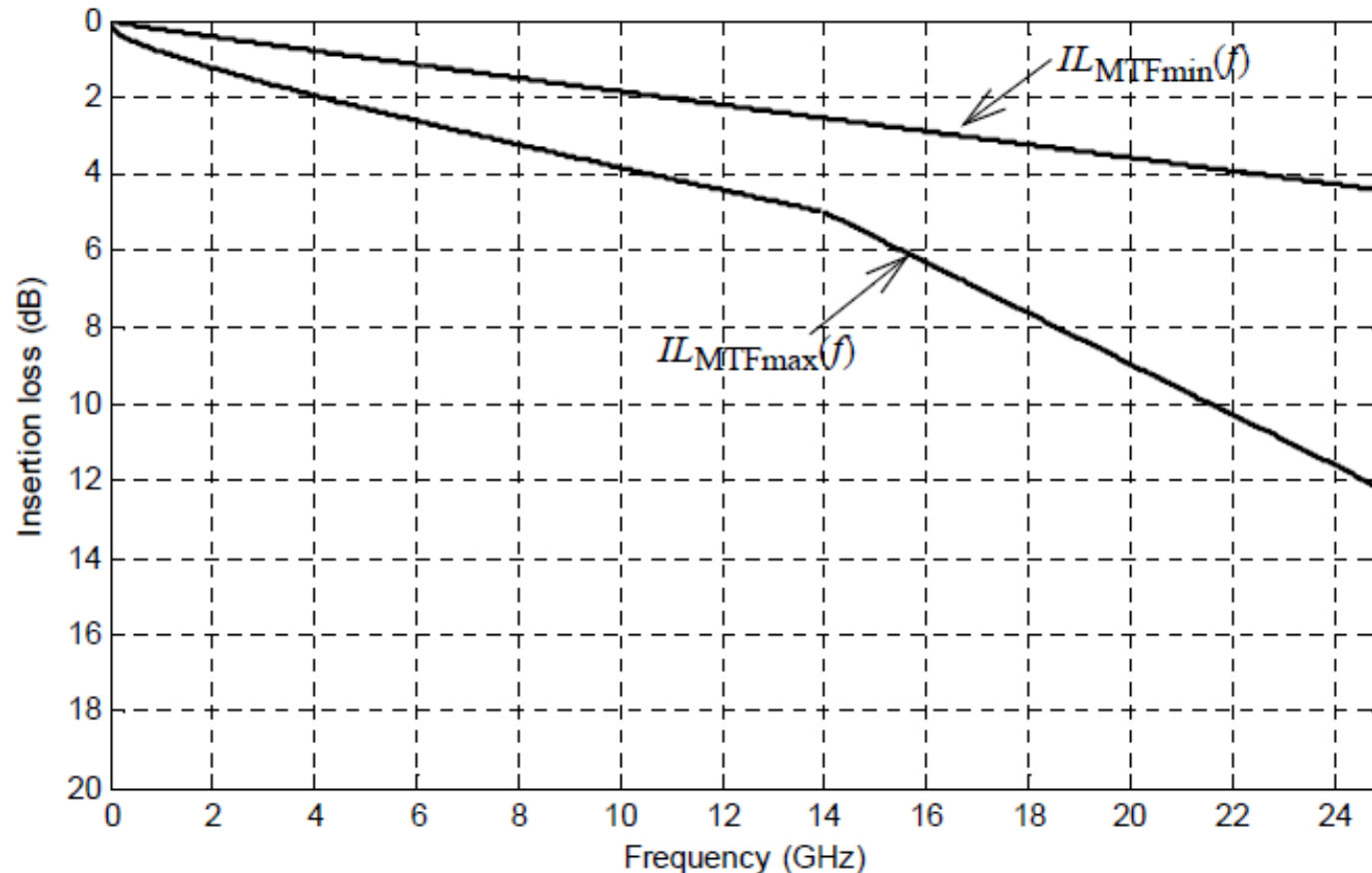
- Same as Annex 83E (CAUI-4 c2m)

# CDAUI-8 c2m Tx Common-Mode to Differential & Rx Differential to Common-Mode Return Loss Specs



- Same as Annex 83E (CAUI-4 c2m)

# Compliance Boards



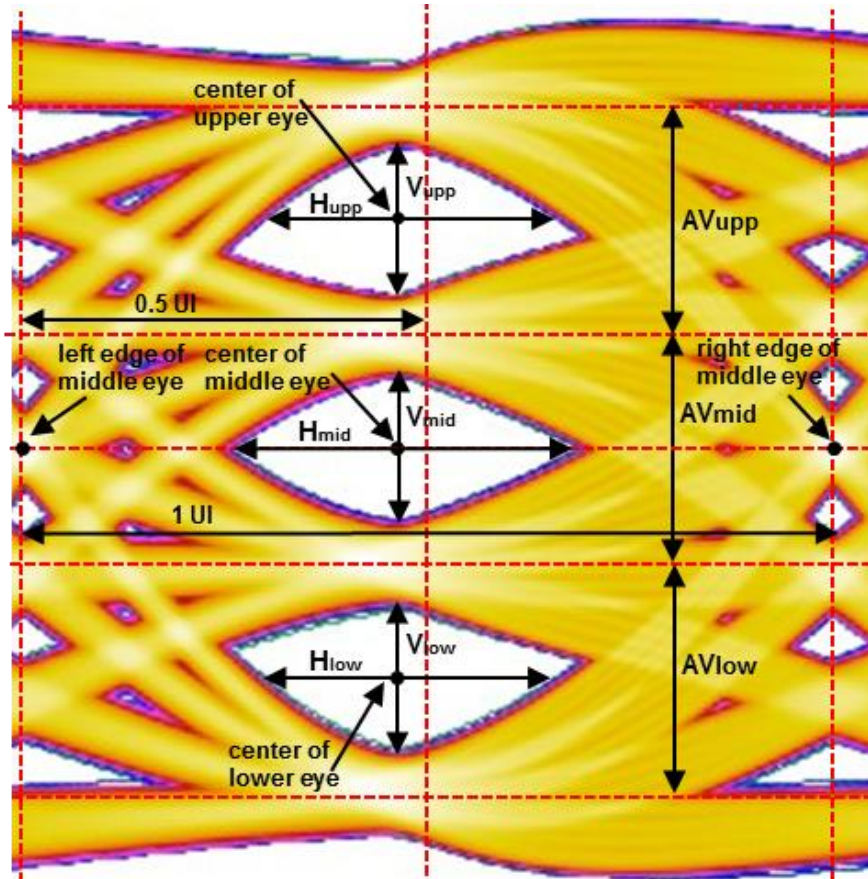
- Same as CR4 (Cl. 92)
  - No new compliance boards required



# CDAUI-8 c2m Test Patterns

- CDAUI-8 PMA can reuse test pattern defined in clause 94.2.9:
  - Quaternary PRBS13 test pattern (if the termination block (i.e., 94.2.2.4) is removed, this will need to be changed accordingly)
  - Other KP4 test patterns (JP03A, JP03B) not required

# CDAUI-8 c2m PAM4 Jitter and Eye Height Parameters



See Appendix for measurement procedure

# Module Stressed Receiver Test

- Same test configuration as Annex 83E
  - Modified for PAM4 testing consistent with 56G-VSR-PAM4
  - CRU and SIJT corner frequencies pending further study

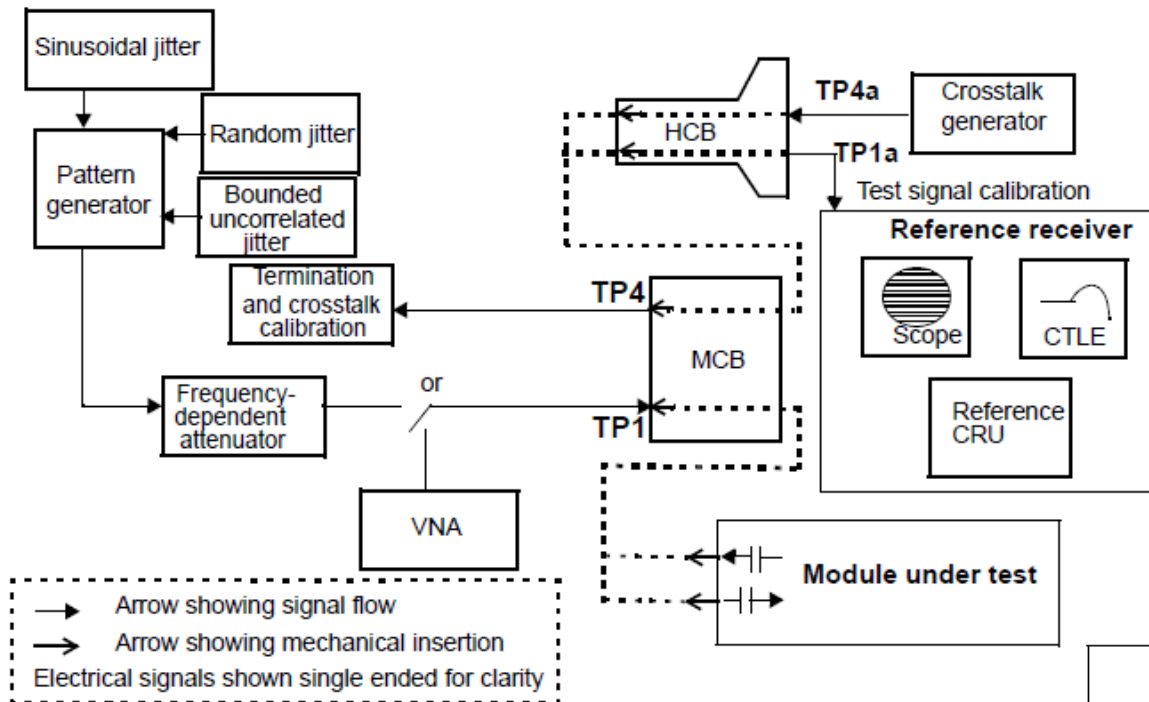


Figure 83E-15—Example module stressed input test

Table 15-7. Sinusoidal jitter frequency for TP4 and TP1 testing

Frequency Range (Hz)	Sinusoidal jitter, Peak to peak (UI)
$f < f_b/849600$	Not Specified
$f_b/849600 < f \leq f_b/8496$	$5 \cdot f_b / (849600 \cdot f)$
$f_b/8496 < f \leq 10 \times LB$	0.05
NOTES: LB = Receiver Loop Bandwidth	

# Host Stressed Receiver Test

- Same test configuration as Annex 83E
  - Modified for PAM4 testing consistent with 56G-VSR-PAM4
  - CRU and SIJT corner frequencies pending further study

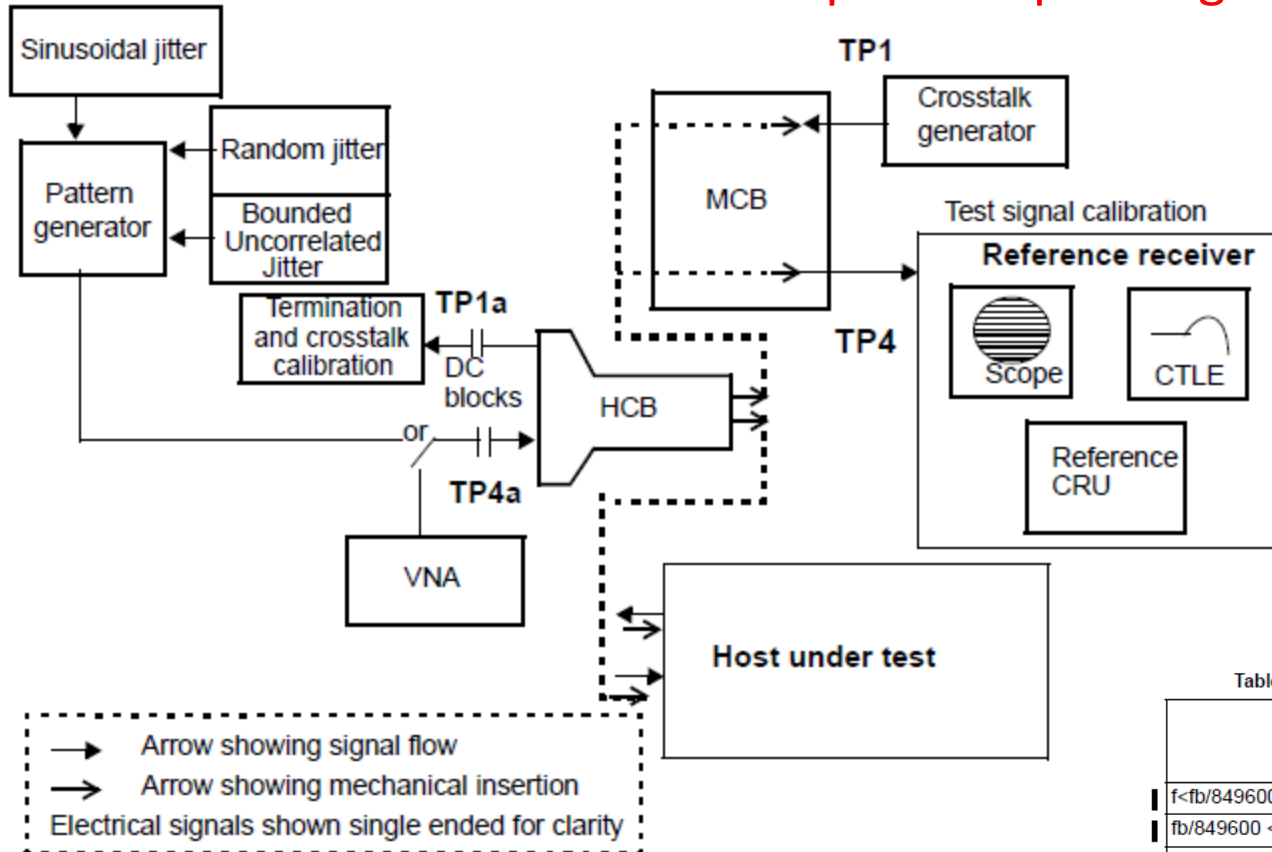


Figure 83E-14—Example host stressed input test

Table 15-7. Sinusoidal jitter frequency for TP4 and TP1 testing

Frequency Range (Hz)	Sinusoidal jitter, Peak to peak (UI)
$f < f_b/849600$	Not Specified
$f_b/849600 < f \leq f_b/8496$	$5 \cdot f_b / (849600 \cdot f)$
$f_b/8496 < f \leq 10 \cdot \text{LB}$	0.05
NOTES: LB = Receiver Loop Bandwidth	

# Host / Module Output Waveform Test \*

- Same test configuration as Annex 83E
  - Modified for PAM4 testing consistent with 56G-VSR-PAM4
  - CRU corner frequency pending further study

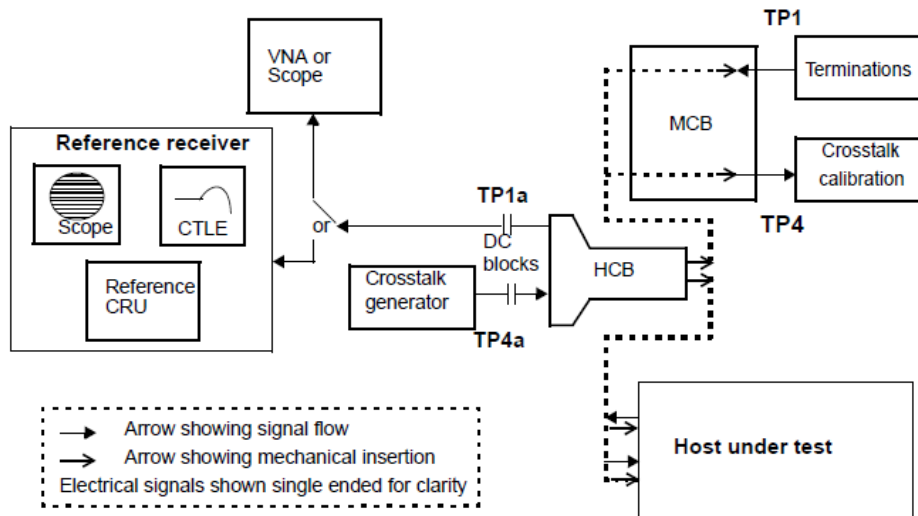


Figure 83E-9—Example host output test configuration

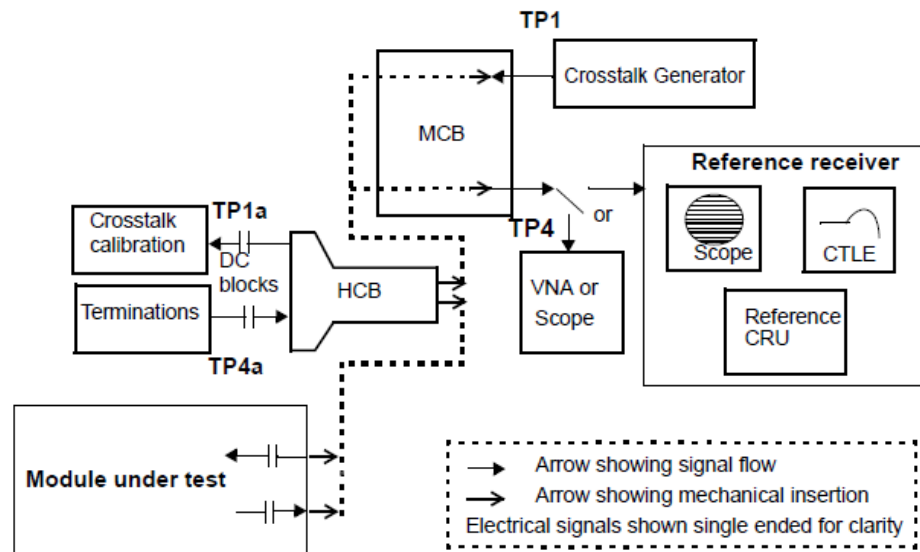


Figure 83E-11—Example module output test configuration

# Summary

- Baseline proposal using PAM4 signaling for a CDAUI-8 c2m electrical interface specification:
  - Supports CAUI-4 c2m channel
  - Reuses test infrastructures and setup in Annex 83E
  - Is consistent with CEI-56G-VSR draft baseline specification
    - Straightforward to extend/modify Annex 83E specification for PAM4 signaling

# References

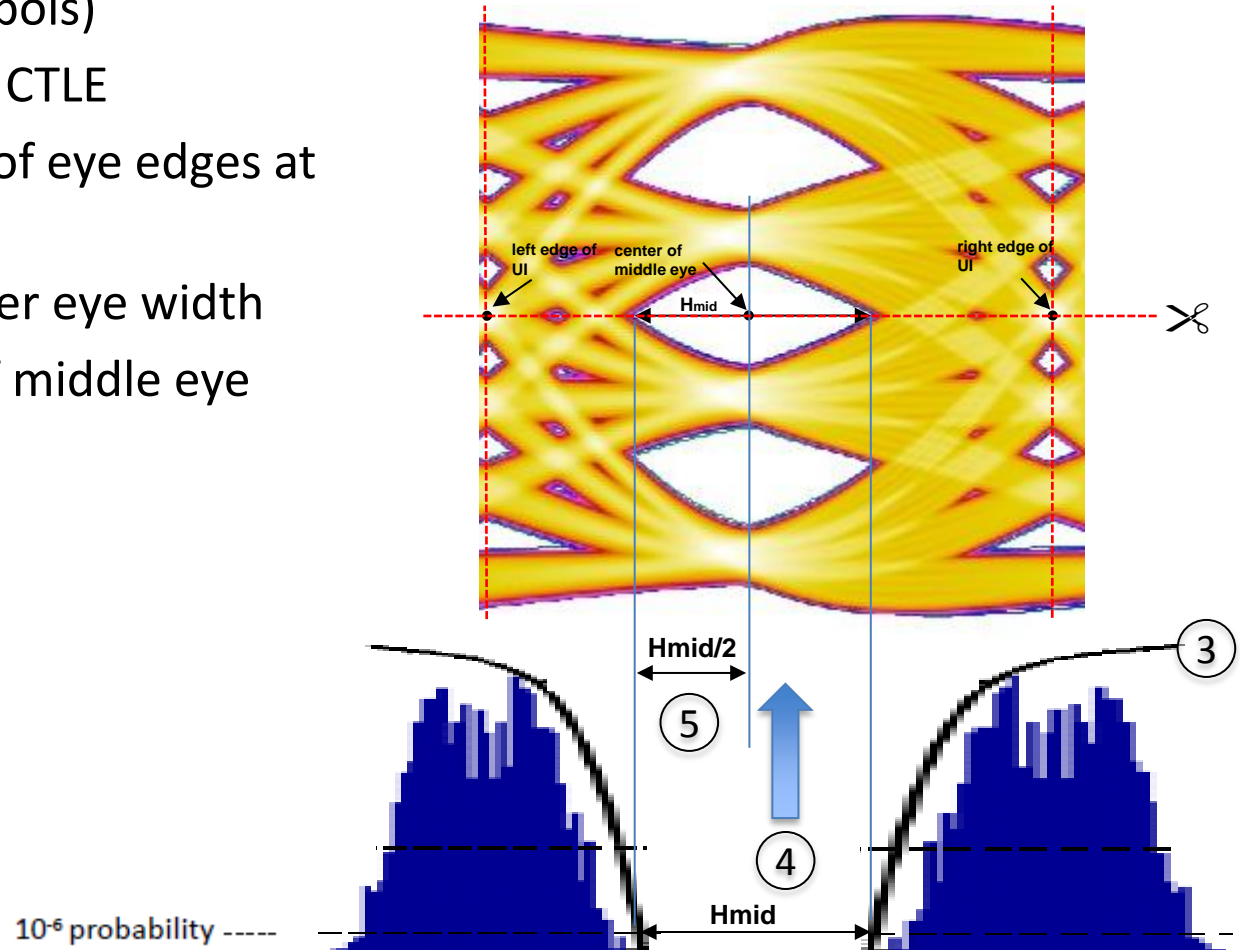
[1] oif.2014.230.01, [www.oiforum.com](http://www.oiforum.com) (This document was provided as an attachment to the October 28, 2014 liaison from OIF to IEEE 802.3. The liaison and its attachments can be found in the IEEE P802.3bs 400 Gb/s Ethernet Task Force private area)

# Appendix

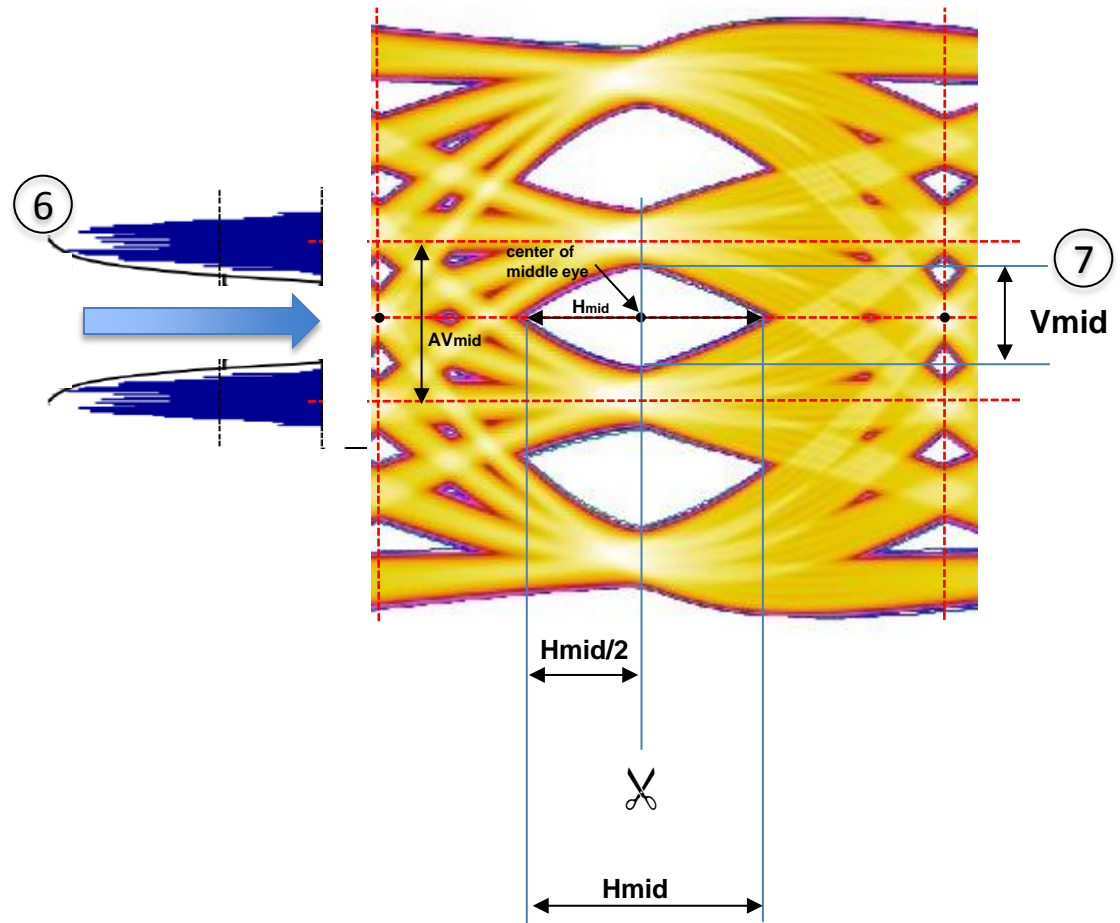
## Extracting PAM4 Eye Width and Height



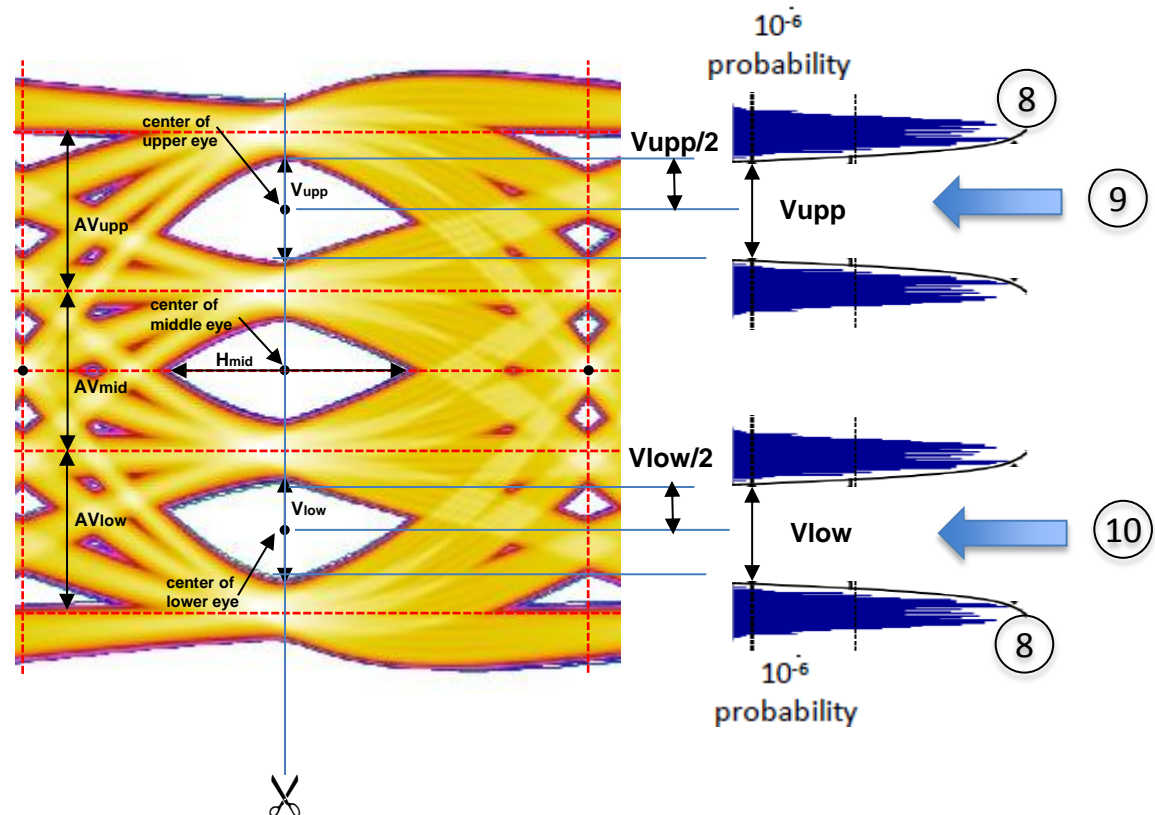
- Reuse Annex 83E.4.2 method to:
  1. Capture QPRBS13 pattern (> 4 million symbols)
  2. Apply reference CTLE
  3. Construct CDFs of eye edges at zero crossing
  4.  $H_{mid} = 1e-6$  inner eye width
  5. Locate center of middle eye at  $H_{mid}/2$



- Reuse Annex 83E.4.2 method to:
  6. Construct CDFs of signal voltages of middle eye sampled at  $H_{mid}/2$
  7.  $V_{mid} = 1e-6$  inner eye height



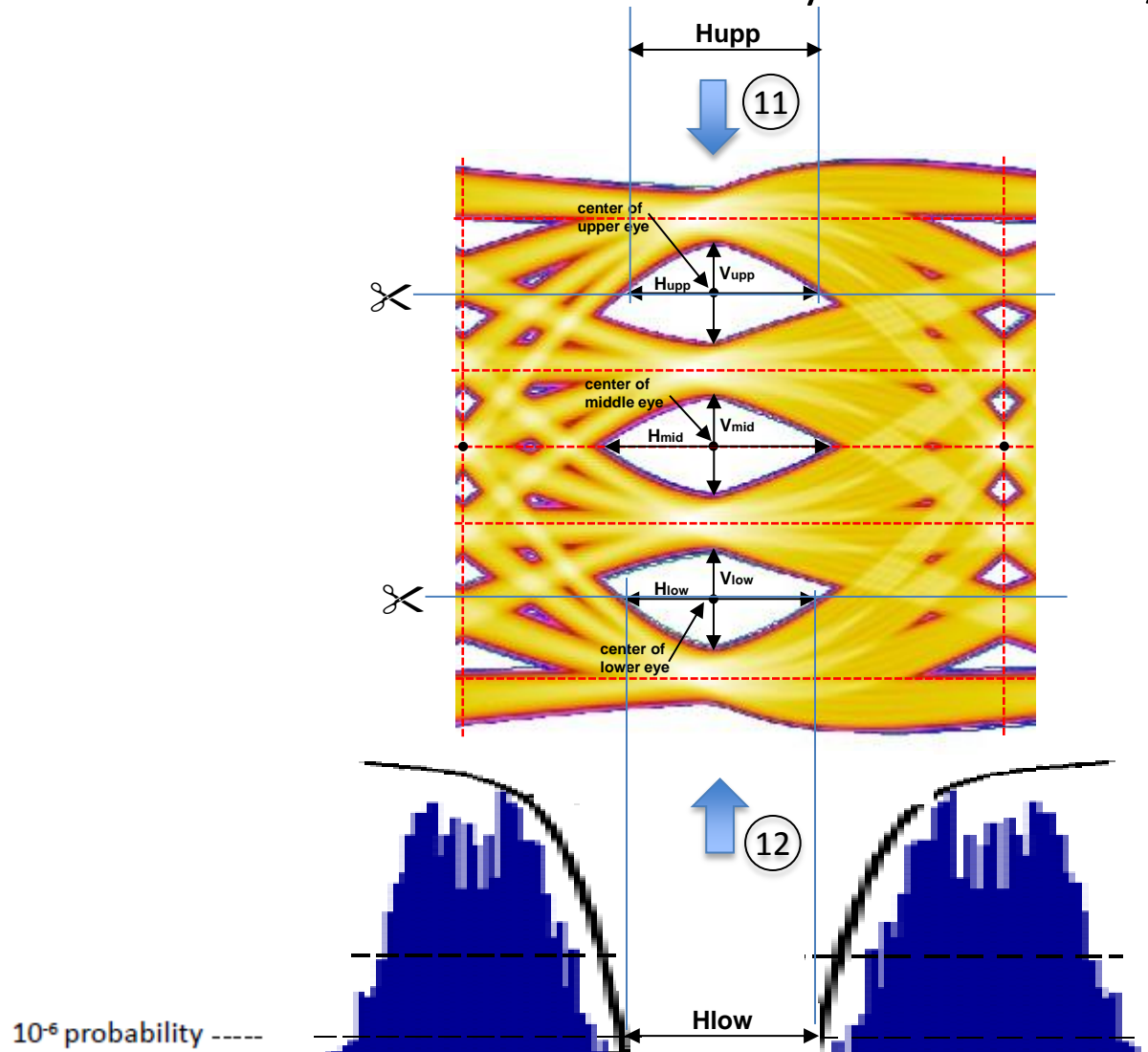
- Extract upper and lower eye heights
  8. Construct CDFs of signal voltages of upper and lower eyes at  $H_{mid}/2$
  9.  $V_{up} = 1e-6$  inner height of upper eye at  $H_{mid}/2$
  10.  $V_{low} = 1e-6$  inner height of lower eye at  $H_{mid}/2$



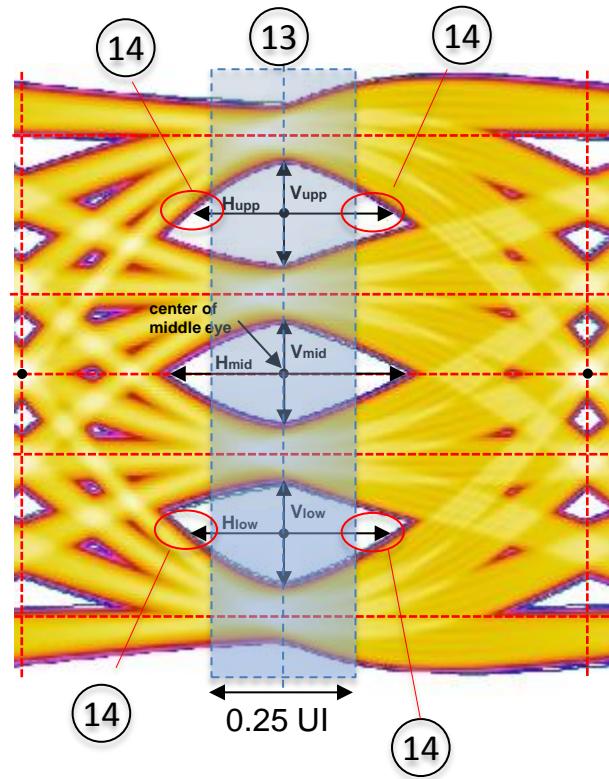
- Extract upper and lower eye widths

11.  $H_{upp} = 1e-6$  inner width of upper eye sliced at  $V_{upp}/2$

12.  $H_{low} = 1e-6$  inner width of lower eye sliced at  $V_{low}/2$

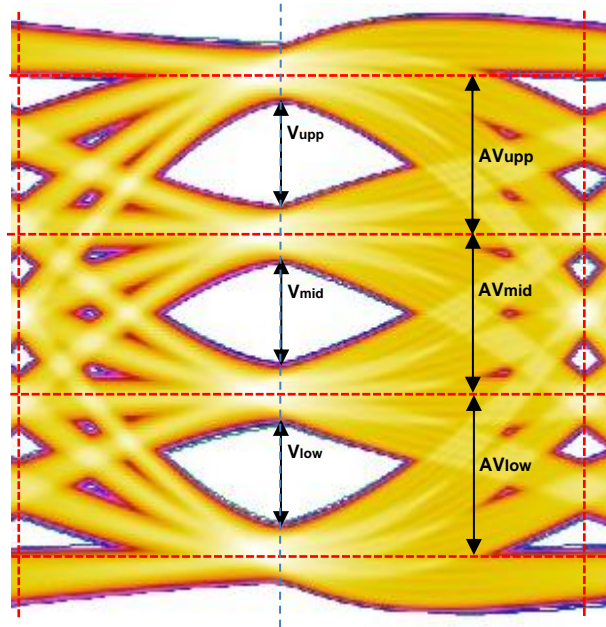


- Check upper and lower eye alignment to middle eye
  13. Apply 0.25UI-wide mask centered on middle eye
  14.  $1e-6$  horizontal openings of upper and lower eyes must extend outside this mask, measured at  $\frac{1}{2}$  inner eye height



- Module Output VEC Measurement

15. Calculate VEC as  $20\log[\min(AV_{upp}/V_{upp}, AV_{mid}/V_{mid}, AV_{low}/V_{low})]$



# Energy Efficient Ethernet (EEE) for 802.3bs

## Arthur Marris - Cadence

# Supporters

- Mark Gustlin – Xilinx
- Andre Szczepanek – Inphi
- Dave Ofelt – Juniper
- Gary Nicholl - Cisco



# Key features of Energy Efficient Ethernet (EEE)

- If a system has nothing to transmit it can power down its transmit path after it has indicated its intention to do so.
- The partner device can also power down its receive path when it detects that the path is going to be powered down.
- The link stays up while in low power mode and no frames are dropped.
- EEE is asymmetric. One direction can be powered up while the other is powered down.

# How does EEE work?

- The client (i.e. system) requests Low Power Idle (LPI) from the reconciliation sublayer (RS).
- The RS then signals LPI on the MII (media independent interface).
- The transmit PCS (physical coding sublayer) encodes the LPI signal using a special symbol.
- The receive PCS decodes the LPI symbol and signals LPI on the receive MII.
- When the client ceases requesting LPI the RS continues inhibiting transmission for a fixed period to allow time for the local transmit path and remote receive path to recover from their low power modes.

# What is “Fast Wake” mode of operation?

- In Fast Wake mode of operation the transmit and receive path remain active and continuously transmit and receive LPI when it is requested by the client. (However Clause 82 BIP is not calculated)
- Fast Wake is compulsory for 40G and 100G PHYs that support EEE.
- Fast Wake is controlled by LLDP (Link Layer Discovery Protocol) rather than AN (auto-negotiation)
- Fast Wake is suitable for optical PHYs that unable to power up and down quickly and do not support AN.

# What is “Deep Sleep” mode of operation?

- In Deep Sleep mode the transmit path stops transmitting but periodically sends refresh indication while LPI is requested.
- In Deep Sleep mode the receiver checks for the occurrence of refresh indication and will assert link failure if refresh does not appear.
- Deep Sleep mode requires the receive PMA and PCS to resume operation within a determined time period.
- In Deep Sleep mode the transmit and receive PCS generate tx\_quiet and rx\_quiet signals to allow the PHY to periodically power down its transmit and receive path.
- Clause 83 defines a mechanism for sending the tx\_quiet signal over the CAUI/XLAUI interface and for synthesizing the rx\_quiet signal.
- As only optical PHYs are included in the 802.3bs objectives, none of the PHYs specified in 802.3bs will support Deep Sleep operation, however the architecture should not preclude support for Deep Sleep in the future.

# What should be done for 802.3bs?

- Adopt Fast Wake mode of operation for the 802.3bs PHY types.
- Add these PHY types to “Table 78-1 Clauses associated with each PHY or interface type” and indicate that they do not support deep sleep with the “b” suffix.
- The CDMII will need to be able to signal LPI and the RS will need to include a transmit LPI state machine to defer transmission for the wake time period after de-assertion of LPI.
- The PCS will need to be able to encode and decode LPI.

# Further considerations for supporting EEE in 802.3bs

- Consider whether the receive PCS should have a “RX\_FW” state that it goes into when receiving LPI from its link partner. In this state it could disable error checking.
- When specifying the CDAUI electrical interface consider defining a mechanism for transmitting alert and quiet signalling similar to how it is done in 83.5.11.1 to allow for future support of Deep Sleep, and also consider generation of an energy detect signal.
- To support Deep Sleep mode the PCS needs to achieve synchronization and alignment quickly. This will most likely be done through the use of “rapid alignment markers” so make sure the architecture does not preclude their use in the future.
- If Deep Sleep is supported in the future then the CDXI may need to be powered down. In this case it would be necessary to preserve the MII signalling of LPI to the PCS in the transmit direction and LPI to the MAC in the receive direction until the interface powers up. Also it will be necessary for the CDXI to power up quickly.

# Summary

- 802.3bs will use EEE fast wake functionality which requires the CDMII to signal LPI and the PCS to encode and decode it
- To allow for future support of deep sleep functionality consideration needs to be given to how the PCS and electrical interfaces can resume operation quickly after power down

# OTN Support Proposal

## P802.3bs 400 Gb/s Ethernet Task Force

Steve Trowbridge  
Alcatel-Lucent



# Supporters

- Pete Anslow (Ciena)
- Gary Nicholl (Cisco)
- Tongtong Wang (Huawei)
- Xinyan Wang (Huawei)
- David Ofelt (Juniper)
- Andre Szczepanek (Inphi)

# Key Elements of OTN Support

- See “[OTN Support: What is it and why is it important?](#)”, July 2013
  - A new rate of Ethernet (e.g., 400 Gb/s) fits into the corresponding rate OTN transport signal
  - All Ethernet PHYs of a given rate are mapped the same way and can be interconnected over the OTN (e.g., same PCS for all 100 Gb/s PHYs gives a single canonical format (“characteristic information” in ITU-T terminology) that can be mapped
  - Optical modules for Ethernet can be reused for OTN IrDI/client interfaces at the corresponding rate

# A new rate of Ethernet (e.g., 400 Gb/s) fits into the corresponding rate OTN transport signal

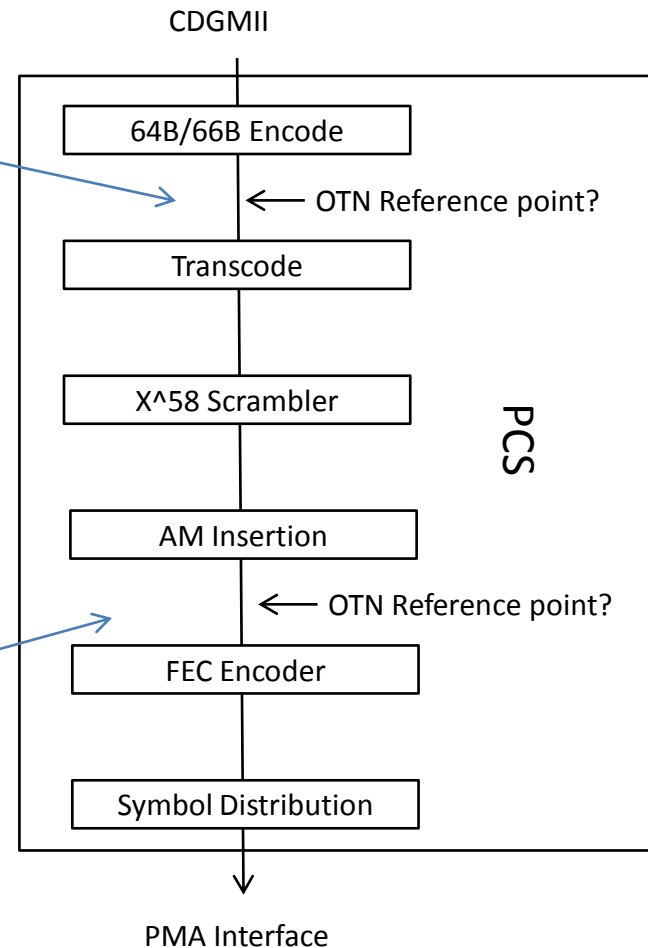
- Assumption – the OTN mapper/demapper will terminate and regenerate any Ethernet FEC code, correcting errors at the OTN ingress since the FEC is chosen to correct single-link errors but not double-link errors
- Assumption – the OTN mapper/demapper may trans-decode/trans-encode back to 64B/66B to avoid MTTFPA reduction for OTN transported signal
- Based on these assumptions, the encoded data rate of the OTN-mapped 400 Gb/s Ethernet would be no more than  $400 \text{ Gb/s} \times 66 / 64 = 412.5 \text{ Gb/s} \pm 100\text{ppm}$ . Since the 400 Gb/s OTN container would presumably be designed to also transport four “lower order” ODU4s, there should be no concern that it is large enough to carry 400 Gb/s Ethernet based on the assumption that the canonical form is near this rate.
- Any Ethernet bits in excess of this rate are likely to be part of a FEC that is not carried over OTN

# All PMDs of a given rate are mapped in the same way into OTN:

Candidate Locations for the OTN Reference point

Option B

Option A



# OTN Reference Point Option A

- Pro
  - Most similar to what ITU-T chose for mapping of 40GbE into OPU3 and 100GbE into OPU4 based on 802.3ba assumption that all PMDs of a given rate used exactly the same logical lane striping
  - Capable of carrying end-to-end information in the alignment markers if all PMDs are striped the same
- Con
  - Even if all P802.3bs PMDs use the same logical lane striping, if all future 400GbE PMDs are not striped in the same way, requires re-striping into the canonical format before mapping into OTN
  - Relies on OTN FEC for satisfactory MTTFPA

# OTN Reference Point Option B

- Pro
  - High certainty to be a common format regardless of whether all 400GbE PMDs (P802.3bs and future) use the same logical lane striping
  - No need to convert between logical lane formats in OTN mapper/demapper
  - Robust MTTFPA regardless of what ITU-T does with FEC
- Con
  - Can't carry end-to-end information in alignment markers. But note that there doesn't seem to be a compelling reason to support BIP inside of FEC-enabled Ethernet PMDs
  - Higher bit-rate to map as 64B/66B rather than mapping the transcoded signal.

# Straw Polls relevant to OTN support

- Straw Poll #1 - I support FEC for optical PMDs
  - **FEC mandatory – 69**
  - FEC optional – 7
  - Some PMDs may not need FEC – 0
  - Mandatory for some, optional for others – 10
  - Need more information – 10
- Straw Poll #9 - If all PMDs developed in P802.3bs include mandatory FEC and FEC error statistics are available, do we also require BIP?
  - Y: 4; **N: 24; A: 69**
- Straw Poll #10 – If BIP is required, should it be:
  - Segment by segment (optimized for fault isolation) – 2
  - End to end (optimized for service assurance) – 6
  - **Need more information – 35**
  - **Not required/don't care - 33**

# Observations

- Strong majority believe that all optical PMDs developed by P802.3bs will have mandatory FEC
- Most think that if all optical PMDs have mandatory FEC, that BIP is not necessary, i.e., you get a better view of link quality from FEC corrected errors
  - Note that any BIP inside of a FEC exhibits a “cliff” behavior, going from zero errors to quite a lot the instant the error ratio exceeds the correction capability of the FEC. In addition, this information is available from the FEC uncorrected codewords counter
- For those who still think there would be BIP, the number who express an opinion on how it is used (fault isolation or service assurance) is statistically insignificant
- For those who still think they need more information, please study slides 5-12 of [trowbridge 3bs 01 0714.pdf](#) and ask questions!



# OTN Reference Point Proposal

- Propose that the OTN reference point for 400GbE is a logically serial stream of 64B/66B blocks, unstriped, without lane alignment markers (Option B). An implication of this choice is that there is no BIP carried end-to-end (note that a segment BIP for a particular lane striping and FEC would still be possible).
- Any idle insertion/deletion to provide room for striping overhead must occur between the CDGMII and the OTN reference point. No idle insertion/deletion should occur between the OTN reference point and the PMD. Assuming 16K frequency of lane markers (regardless of the lane count or lane rate), the effective rate of this logical interface is the *nominal MAC rate*  $\times 66/64 \times (1 - 1/16384)$  so that any physical instantiation has room to insert lane markers as needed without idle insert/delete elsewhere in the stack

# Module Reuse

- Module reuse was facilitated by the fact that nothing below a CAUI chip-to-module interface cared about the or manipulated the bit values on the lanes – as long as OTN was striped into the same number of logical lanes as Ethernet, everything would work
- The following likely can be preserved: no idle insertion/deletion occurs below a CDAUI chip-to-module interface
- The following are possibly not be precluded by the 400GbE architecture:
  - Logical to physical lane multiplexing in a module may be on a block or FEC symbol basis rather than a bit basis
  - One (possibly Ethernet Frame Format dependent) FEC code may be replaced with another)

# Options for Module Reuse

- Option I: Preserve the 802.3ba rule that no sublayers below a CDAUI care about bit values or manipulate the bit values on logical lanes (bit multiplexing only). Any FEC is done on the host board above a CDAUI. OTN may use a different FEC than Ethernet if it needs a stronger FEC to compensate for the higher bit-rate
- Option II (most general, described in Norfolk) encode the OTN frame as 66B blocks (all data) and use whatever striping and FEC encoding mechanisms are used for Ethernet. OTN and Ethernet use the same FEC
- Option III (potentially very complex) Allow OTN to use a different (stronger) FEC than Ethernet but do not require bit multiplexing of logical lanes. This would constrain that OTN and Ethernet choose FEC (or pairs of FECs, if not all 400GbE PMDs use the same FEC) with the same symbol size and that the marking to discover the FEC symbol alignment is common between OTN and Ethernet

# Option II Amplification

- Use the fact that the OTN reference point, as proposed, is a logically serial stream of 64B/66B blocks.
- Note that before this reference stream can be physically instantiated, it must be striped over multiple physical or logical lanes
- Maintain the principle, as in 802.3ba, that idle insertion/deletion is not done below this reference point.

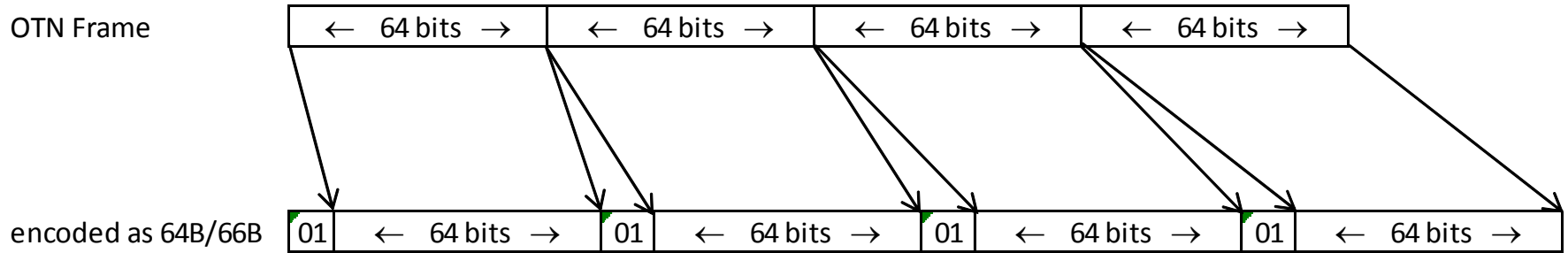
# Option II Example

- Example physical instantiation could be something like [gustlin 400 02a 1113.pdf](#), produced by transcoding 64B/66B to 256B/257B, striping first into 100G groups, striping within each 100G group into 4 logical lanes on 10-bit symbol boundaries, inserting alignment markers on each lane, and applying an RS(528,514) code based on 10-bit symbols with alignment markers appearing in the first of each of 4096 Reed Solomon code blocks (essentially 4 instances of P802.3bj 100G FEC)

# Option II Implications for OTN

- Likely only possible if the same FEC code can be used for OTN applications as for Ethernet applications at about 6% higher bit-rate
- Would need to make OTN look like 66B blocks. Easiest way to do this and not lose any information in transcoding is to insert a “01” sync header after every 64 bits (all data)
- Since this is just part of the logical frame format, this doesn't waste as many bits as it appears. 8 sync header bits are added to every 256 data bits in the “logical” frame format, but 7 of those bits are immediately recovered in 256B/257B transcoding and reused for the FEC code. So 0.39% net is added to the OTN frame to make it look like 66B blocks, then 2.724% overhead RS FEC added

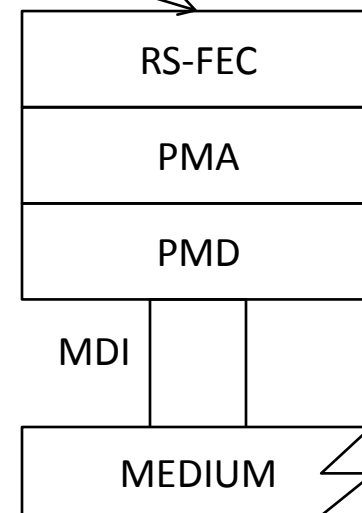
# Option II - Illustration of turning OTN frame into 64B/66B blocks



Use the Ethernet Stack to stripe and FEC encode the OTN frame when carrying over an Ethernet Module for an OTN IrDI or client interface

Could be OTN frame aligned as an OTUC4 frame without FEC is exactly  $7648 \times 64$  bits, but not essential with scrambling

Scramble



# Option II: OTN Bit-rates using this scheme

	Working Assumption Bit-Rate
OTUC4 bit-rate without FEC	422.904 Gb/s
64B/66B encoded	436.120 Gb/s
256B/257B transcoded	424.556 Gb/s
Insert Lane Markers	424.582 Gb/s
Add RS(528,514) FEC	436.146 Gb/s
Logical Lane Rate (well within CEI-28G)	27.259 Gb/s
Ethernet Nominal Bit-rate	412.5 Gb/s
400G OTN Increase in bit-rate	5.73 %

100G OTN Increase in bit-rate	8.42 %
-------------------------------	--------

Smaller increase for 400G than for 100G, mainly due to RS(528,514) FEC rather than RS(255,239) FEC. Proportion remains the same even for Ethernet PMDs that use a higher overhead FEC



## Option II – Recommended module reuse mechanism for OTN

- There is an Ethernet sublayer reference point such as the that is logically equivalent to a serial stream of 64B/66B blocks (the same as the recommended OTN reference point)
- No idle insertion/deletion occurs below the that reference point, and hence the rest of the stack can deal with a constant-bit-rate (CBR) bitstream that is effectively an infinite-length packet.
- Note that any logical to physical lane interleaving that works for Ethernet also works for OTN since they are encoded the same way
- The link parameters and FEC coding gain have sufficient margin to meet the error performance target when running at approximately 5.73% higher bit-rate than necessary for 400G Ethernet

THANKS!

# 400 Gb/s 100 m MMF reach objective draft baseline proposal

MMF ad hoc

IEEE P802.3bs, San Antonio, TX, Nov 2014

# Outline

- Baseline proposal of a retimed PMD to address the 802.3bs objective to ‘Provide physical layer specifications which support link distances of at least 100 m over MMF’
  - 16 lane parallel, short wavelength based PMD for 400GBASE-SR16.
  - Leveraging 100GBASE-SR4 technology, compatible with 16 x 25 Gb/s electrical interface, and breakout applications.
  - Assumed use of 100GBASE-SR4 FEC, or similar strength FEC (to be defined in 802.3bs), to enable 100 m reach.
  - Architecture, parameters and specifications for optical interfaces, and the proposed MDI, follow.

# Supporters and contributors

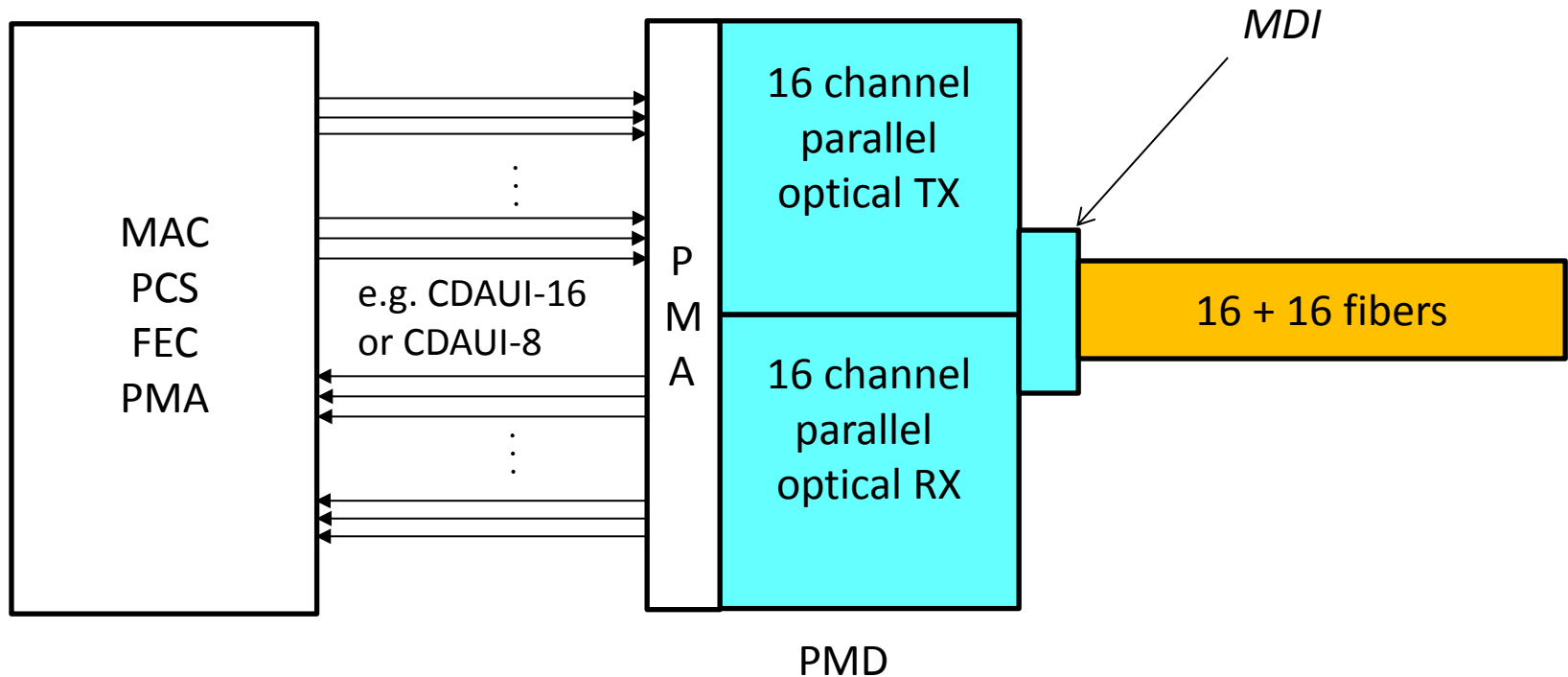
- John Abbott, Corning
  - Piers Dawe, Mellanox
  - Mike Dudek, QLogic
  - Ali Ghiasi, Ghiasi Quantum LLC
  - Mark Gustlin, Xilinx
  - Jack Jewell, Commscope
  - Jonathan King, Finisar
  - Scott Kipp, Brocade
  - Paul Kolesar, Commscope
  - Brett Lane, Panduit
  - Robert Lingle Jr., OFS
  - Valerie Maguire, Siemon
  - Slobodan Milijevic, Microsemi
  - John Petrilla, Avago technologies
  - Rick Pimpinella, Panduit
  - Rick Rabinovich, Alcatel-Lucent Enterprise
  - Steve Swanson, Corning
  - Mike Zhang, Siemon
- and a very nice letter of support  
from the CDFP MSA

# Motivation

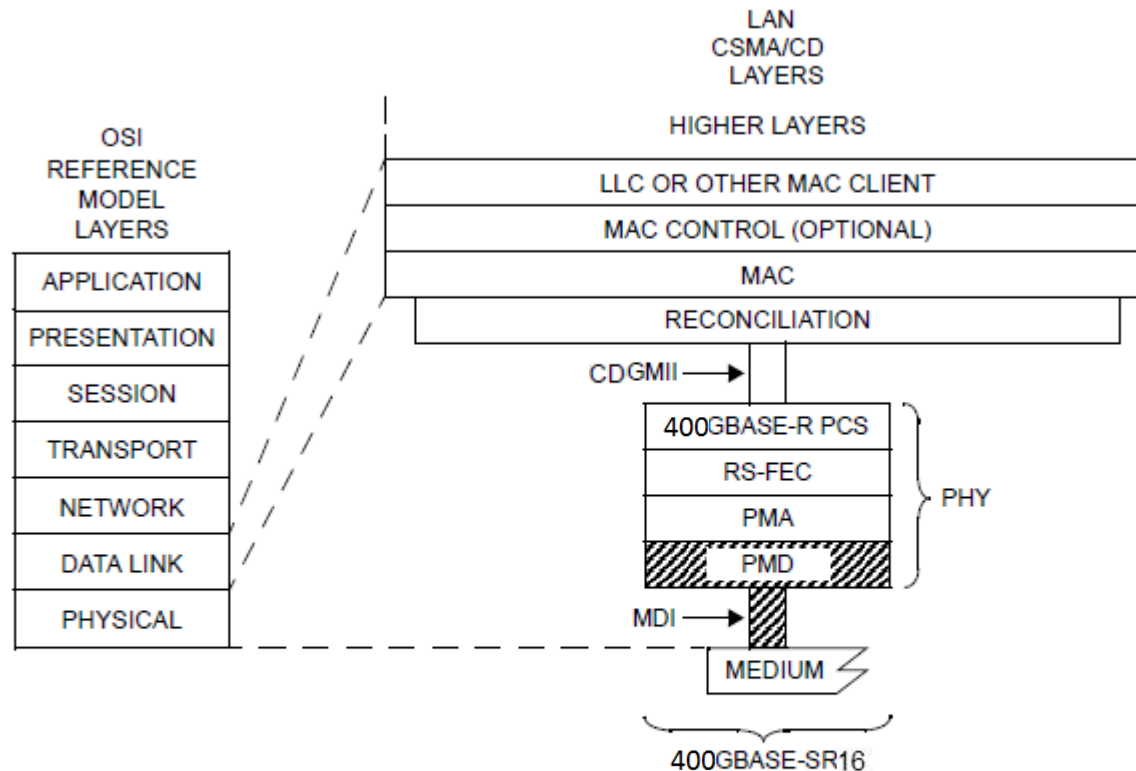
- 16 parallel links operating at 25.78125 GBd utilize low cost, high performing multimode fiber compatible optics and electronics
  - Leverages 100GBASE-SR4 technology
  - FEC supported retimed interface enables a lowest power, lowest cost, 100m solution today
  - Uses existing, viable semiconductor technologies and uncooled VCSELs
- The 16 optical lanes can directly map the 16 electrical lanes of CDAUI-16, without requiring multiplexing, translation, or de-skewing inside the module.
- Compatible with 'break out' application
- This proposal is supported by multiple vendors and users, and is economically feasible and competitive compared to other alternatives.

# Proposal

- 16 parallel lanes @ 25.78125 GBd for 100GBASE-SR16 over 100 m OM4 fiber.
  - Exact signaling rate is determined by project's choice of FEC.
- 850 nm sources, re-use of 100GBASE-SR4 specifications.
  - Assumes PMD target BER (prior to error correction) around  $5 \times 10^{-5}$ , similar to 100GBASE-SR4.



# Position in 802.3 architecture



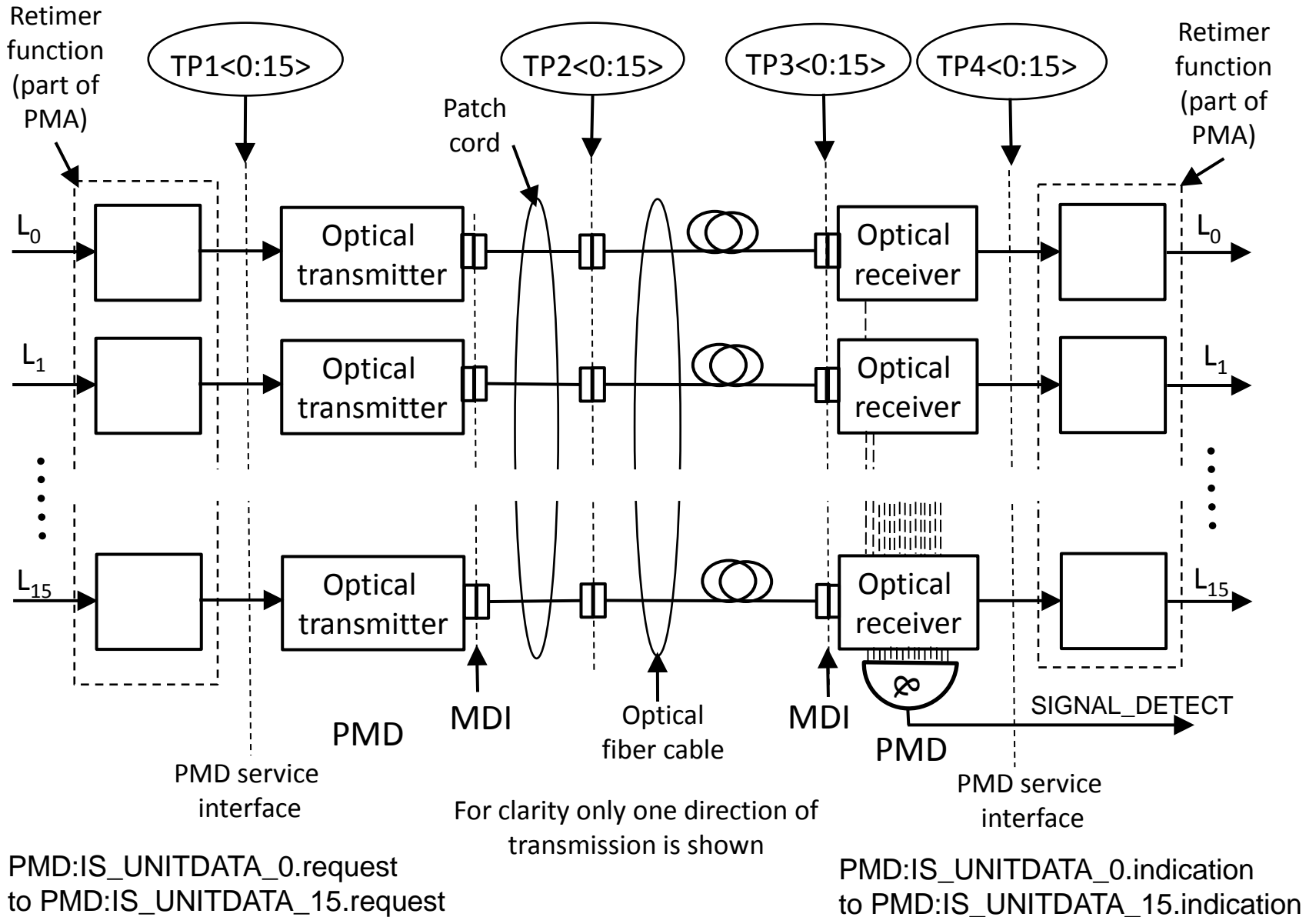
CDGMII = 400 Gb/s MEDIA INDEPENDENT INTERFACE  
 LLC = LOGICAL LINK CONTROL  
 MAC = MEDIA ACCESS CONTROL  
 MDI = MEDIUM DEPENDENT INTERFACE  
 PCS = PHYSICAL CODING SUBLAYER

PHY = PHYSICAL LAYER DEVICE  
 PMA = PHYSICAL MEDIUM ATTACHMENT  
 PMD = PHYSICAL MEDIUM DEPENDENT  
 RS-FEC = REED-SOLOMON FORWARD ERROR CORRECTION  
 SR = PMD FOR MULTIMODE FIBER

*Editor's note: The RS-FEC layer may be merged into 400GBASE-R PCS layer, depending on the choice of architecture by the Task Force.*



# Block diagram for 400GBASE-SR16 transmit/receive path



# PMD Optical specifications

- Transmitter characteristics (each lane) at TP2 follow 100GBASE-SR4, Clause 95, Table 95-6.
- Receiver characteristics (each lane) at TP3 follow 100GBASE-SR4, Clause 95, Table 95-7.
- Illustrative link power budget follows 100GBASE-SR4, Clause 95, Table 95-8.
  - Current status of these tables shown on next 3 slides

Transmitter characteristics (each lane) at TP2:  
follow 100GBASE-SR4, Clause 95, Table 95-6 (D3.2 illustrated below)

Description	Value	Unit
Signaling rate, each lane (range)	$25.78125 \pm 100$ ppm	GBd
Center wavelength (range)	840 to 860	nm
RMS spectral width <sup>a</sup> (max)	0.6	nm
Average launch power, each lane (max)	2.4	dBm
Average launch power, each lane (min)	-9	dBm
Optical Modulation Amplitude (OMA), each lane (max)	3	dBm
Optical Modulation Amplitude (OMA), each lane (min) <sup>b</sup>	-7	dBm
Launch power in OMA minus TDEC (min)	-7.9	dBm
Transmitter and dispersion eye closure (TDEC), each lane (max)	4.9	dB
Average launch power of OFF transmitter, each lane (max)	-30	dBm
Extinction ratio (min)	2	dB
Optical return loss tolerance (max)	12	dB
Encircled flux <sup>c</sup>	$\geq 86\%$ at $19\text{ }\mu\text{m}$ $\leq 30\%$ at $4.5\text{ }\mu\text{m}$	
Transmitter eye mask definition {X1, X2, X3, Y1, Y2, Y3} Hit ratio $1.5 \times 10^{-3}$ hits per sample	{0.3, 0.38, 0.45, 0.35, 0.41, 0.5}	

<sup>a</sup>RMS spectral width is the standard deviation of the spectrum.

<sup>b</sup>Even if the TDEC < 0.9 dB, the OMA (min) must exceed this value.

<sup>c</sup>If measured into type A1a.2 or type A1a.3 50  $\mu\text{m}$  fiber in accordance with IEC 61280-1-4.

## Receiver characteristics (each lane) at TP3: follow 100GBASE-SR4, Clause 95, Table 95-7 (D3.2 illustrated below)

Description	Value	Unit
Signaling rate, each lane (range)	25.78125 ± 100 ppm	GBd
Center wavelength (range)	840 to 860	nm
Damage threshold <sup>a</sup> (min)	3.4	dBm
Average receive power, each lane (max)	2.4	dBm
Average receive power, each lane <sup>b</sup> (min)	-10.9	dBm
Receive power, each lane (OMA) (max)	3	dBm
Receiver reflectance (max)	-12	dB
Stressed receiver sensitivity (OMA), each lane <sup>c</sup> (max)	-5.6	dBm
Conditions of stressed receiver sensitivity test: <sup>d</sup>		
Stressed eye closure (SEC), lane under test	4.9	dB
Stressed eye J2 Jitter, lane under test	0.39	UI
Stressed eye J4 Jitter, lane under test	0.53	UI
OMA of each aggressor lane	3	dBm
Stressed receiver eye mask definition {X1, X2, X3, Y1, Y2, Y3} Hit ratio $5 \times 10^{-5}$ hits per sample	{0.28, 0.5, 0.5, 0.33, 0.33, 0.4}	

<sup>a</sup>The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level on one lane. The receiver does not have to operate correctly at this input power.

<sup>b</sup>Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.

<sup>c</sup>Measured with conformance test signal at TP3 (see 95.8.8) for the BER specified in 95.1.1.

<sup>d</sup>These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

Illustrative link power budget:  
follow 100GBASE-SR4, Clause 95, Table 8 (D3.2 illustrated below)

Parameter	OM3	OM4	Unit
Effective modal bandwidth at 850 nm <sup>a</sup>	2000	4700	MHz.km
Power budget (for max TDEC)	8.2		dB
Operating distance	0.5 to 70	0.5 to 100	m
Channel insertion loss <sup>b</sup>	1.8	1.9	dB
Allocation for penalties <sup>c</sup> (for max TDEC)	6.3		dB
Additional insertion loss allowed	0.1	0	dB

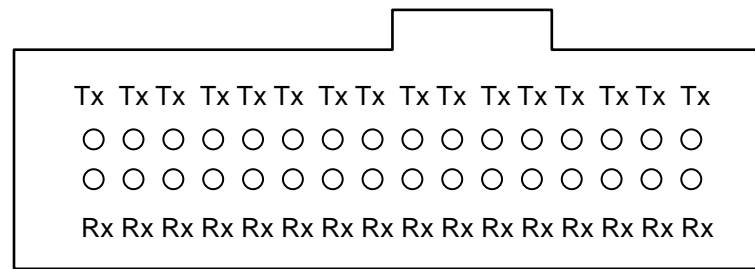
<sup>a</sup>per IEC 60793-2-10.

<sup>b</sup>The channel insertion loss is calculated using the maximum distance specified in Table 95–5 and cabled optical fiber attenuation of 3.5 dB/km at 850 nm plus an allocation for connection and splice loss given in 95.11.2.1.

<sup>c</sup>Link penalties are used for link budget calculations. They are not requirements and are not meant to be tested.

# Medium Dependent Interface (MDI) for 400GBASE-SR16 and lane assignments

- Similar to the MDI defined for 100GBASE-SR10 (Clause 86.10.3.3, Recommended Option A), but using MPO-16, a 16-wide version of the 100G-SR10 MDI.
- Transmitters occupy the top row and receivers occupy the bottom row for better heat dissipation



400GBASE-SR16 optical lane assignments for the MDI receptacle when viewed looking into the receptacle with keyway feature on top.

- The following 4 slides show draft text and figures which describe the MDI and lane assignments, using clause 86 and 95 content as basis, with modifications for 400GBASE-SR16 and MPO-16

# MDI (1 of 4)

## xx.m.n Medium Dependent Interface (MDI)

The 400GBASE-SR16 PMD is coupled to the fiber optic cabling at the MDI. The MDI is the interface between the PMD and the “fiber optic cabling” (as shown in Figure xx-a). The 400GBASE-SR16 PMD is coupled to the fiber optic cabling through one connector plug into the MDI optical receptacle as shown in Figure xx-b. Example constructions of the MDI include the following:

- a) PMD with a connectorized fiber pigtail plugged into an adapter;
- b) PMD with receptacle.

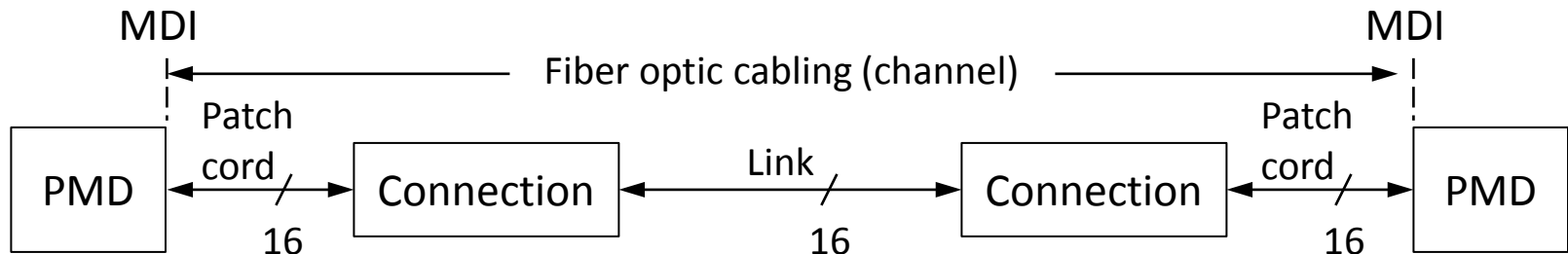


Figure xx-a – Fiber optic cabling model

*Editor's note: Figure xx-a may be placed in a preceding subclause*

# MDI (2 of 4)

## xx.m.n.1 Optical lane assignments

The sixteen transmit and sixteen receive optical lanes of 400GBASE-SR16 shall occupy the positions depicted in Figure xx-b viewed looking into the MDI receptacle with the connector keyway feature on top. The interface contains 32 active lanes within 32 total positions. The transmit optical lanes occupy the top row. The receive optical lanes occupy the bottom row. See clause xx.m.n.2 for MDI optical connector requirements.

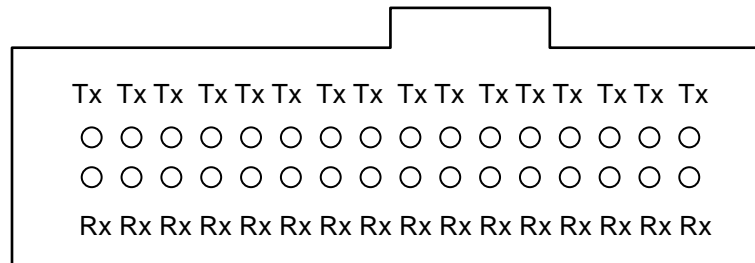


Figure xx-b -- 400GBASE-SR16 optical lane assignments viewed looking into the MDI receptacle with keyway feature on top.



# MDI (3 of 4)

## **xx.m.n.2 Medium Dependent Interface (MDI) requirements**

The MDI adapter or receptacle shall meet the dimensional specifications of ANSI/TIA-604-18 adapter designation FOCIS 18A-k-0. The plug terminating the optical fiber cabling shall meet the dimensional specifications of ANSI/TIA-604-18 female plug connector flat interface designation FOCIS 18P-2x16-1-0-2-2. The MDI shall optically mate with the plug on the optical fiber cabling. Figure xx-c shows an MPO-16 female plug connector with flat interface, and an MDI.

The MDI connection shall meet the interface performance specifications of IEC 61753-1 and IEC 61753-022-2.

NOTE— Transmitter compliance testing is performed at TP2 as defined in xx.k.j, not at the MDI.

*Editor's note: ANSI/TIA-604-18 presently entering third ballot.  
IEC has not yet initiated ballot on the equivalent connector.*

# MDI (4 of 4)

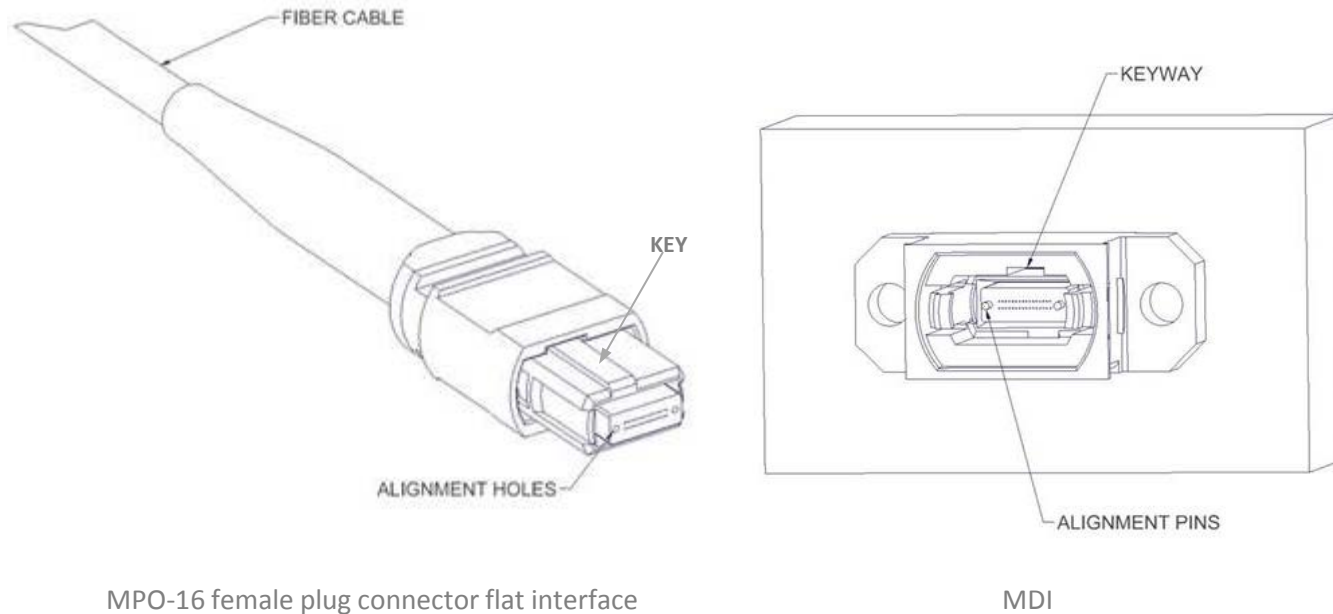


Figure xx-c – MPO-16 female plug connector flat interface and MDI

*Editor's note: Figure is in public domain so may be used "as is". It is also acceptable redrawn in a form like Figure 86-8 with keying adjustment.*

# Further work

- The PMD target BER is likely to deviate from  $5 \times 10^{-5}$ , so some fine tuning of parameters may be required.
  - The project's choice of FEC will determine the pre-FEC BER target, and may also affect the exact signaling rate.
- Confirm skew budget

# **400Gb/s 2km & 10km duplex SMF PAM-4 PMD Baseline Specifications**

---

400 Gb/s Ethernet Task Force

IEEE 802.3 Interim Meeting

18 – 20 May 2015

Pittsburgh, PA

Chris Cole, Finisar

Jeffery J. Maki, Juniper Networks

Atul Srivastava, NTT Electronics

Peter Stassar, Huawei

# Supporters

---

## End Users

- Ralf-Peter Braun, Deutsche Telekom
- Martin Carroll, Verizon
- Derek Cassidy, British Telecom & ICRG
- Lu Huang, China Mobile
- Junjie Li, China Telecom
- Ichiro Ogura, PETRA
- Sam Sambasivan, ATT
- Shikui Shen, China Unicom
- Masahito Tomizawa, NTT
- Guangquann Wang, China Unicom
- Haiyi Zhang, CAICT (CATR)
- Glenn Wellbrock, Verizon
- Wenyu Zhao, CAICT(CATR)

## System OEMs

- Peter Anslow, Ciena
- Marc Bohn, Coriant
- Ayla Chang, Huawei
- Scott Kipp, Brocade
- Andy Moorwood, Ericsson
- David Ofelt, Juniper
- Petar Pepeljugoski, IBM
- Ted Sprague, Infinera
- Tsutomu Tajima, NEC
- Steve Trowbridge, ALU
- Xinyuan Wang, Huawei
- Chengbin Wu, ZTE
- Yu Xu, Huawei

# Supporters, cont.

---

## Test Equipment OEMs

- Thananya Baldwin, Ixia
- Paul Brooks, JDSU T&M
- Greg Lecheminant, Keysight
- Edward Nakamoto, Spirent
- Sergio Prestipino, Exfo
- Pavel Zivny, Tektronix

## Suppliers

- John Abbott, Corning
- Dan Dove, DNS
- Mark Gustlin, Xilinx
- Eric Hall, Aurion
- Jonathan Ingham, Avago
- Jonathan King, Finisar
- Robert Lingle, Jr., OFS
- Alan McCurdy, OFS
- Vasudevan Parthasarathy, Broadcom
- Rick Pimpinella, Panduit

# Select Preceding References

---

- Sept. 2014: 8x50G WDM Technology background  
[http://www.ieee802.org/3/bs/public/14\\_09/stassar\\_3bs\\_01b\\_0914.pdf](http://www.ieee802.org/3/bs/public/14_09/stassar_3bs_01b_0914.pdf)
- Nov. 2014: Nominal Specifications  
[http://www.ieee802.org/3/bs/public/14\\_11/cole\\_3bs\\_02a\\_1114.pdf](http://www.ieee802.org/3/bs/public/14_11/cole_3bs_02a_1114.pdf)
- Jan. 2015: Updated Nominal Specifications  
[http://www.ieee802.org/3/bs/public/15\\_01/cole\\_3bs\\_02\\_0115.pdf](http://www.ieee802.org/3/bs/public/15_01/cole_3bs_02_0115.pdf)
- BTI  
[http://www.ieee802.org/3/bs/public/15\\_01/big\\_ticket\\_items\\_3bs\\_01\\_0115.pdf#page=13](http://www.ieee802.org/3/bs/public/15_01/big_ticket_items_3bs_01_0115.pdf#page=13)  
[http://www.ieee802.org/3/bs/public/15\\_01/big\\_ticket\\_items\\_3bs\\_01\\_0115.pdf#page=19](http://www.ieee802.org/3/bs/public/15_01/big_ticket_items_3bs_01_0115.pdf#page=19)

# Discussion

---

- During the March 2015 P802.3bs TF meeting 50G PAM-4 RX Sens. (inner eye OMA) data was presented
  - Finisar RX Sens. =  $\sim -13.5\text{dBm}$  (BER =  $2\text{e-}4$ )  
[http://www.ieee802.org/3/bs/public/15\\_03/cole\\_3bs\\_02\\_0315.pdf#page=24](http://www.ieee802.org/3/bs/public/15_03/cole_3bs_02_0315.pdf#page=24)
  - Huawei RX Sens. =  $\sim -18\text{dBm}$  (BER =  $2\text{e-}4$ )  
[http://www.ieee802.org/3/bs/public/15\\_03/stassar\\_3bs\\_01a\\_0315.pdf#page=5](http://www.ieee802.org/3/bs/public/15_03/stassar_3bs_01a_0315.pdf#page=5)
- Since the meeting, below deltas were identified:

Parameter	Finisar	Huawei
Noise Current	16.5pA/ $\sqrt{\text{HZ}}$	15pA/ $\sqrt{\text{HZ}}$
PD responsivity	0.5A/W	0.85A/W
Pattern	SSPR	PRBS15
GBaud	28	25.8

- With 0.8A/W PD responsivity, Finisar has since measured RX Sens. =  $\sim -17\text{dBm}$  (BER =  $2\text{e-}4$ )



# Discussion, cont.

---

- -17 to -18dBm OMA RX Sens. enables 2km and 10km 8x50G PAM-4 PMDs using PIN PD RX
- Optical margin for 2km PMD results in sufficiently high manufacturing yield
- Optical margin for 10km PMD results in lower manufacturing yield
- Manufacturing a combination of 2km and 10km PMDs results in sufficiently high yield
- 25G linear APD technology when commercialized will have acceptable stand-alone 10km PMD manufacturing yield, although at a higher cost than PIN PD

# Transmit Characteristics

Description (Outer Eye)	400GBASE-FR8	400GBASE-LR8	Unit
Reach	2	10	km
Signaling Rate, each lane	26.6	26.6	GBd
Operating BER*	2.0E-04	2.0E-04	
Total average launch power (max)	13.2	13.2	dBm
OMA, each lane (max)	5.5	5.7	dBm
OMA, each lane (min)	0.0	0.5	dBm
Launch Power in OMA – TDP, each lane (min)	-1.0	-0.5	dBm
Transmitter and dispersion penalty, (TDP) each lane (max)	2.0	2.2	dB
Extinction ratio (ER) (min)	4.5	4.5	dB
RIN OMA (max)	TBD	TBD	dB/Hz
Optical return loss tolerance (max)	TBD	TBD	dB

\* The exact operating BER will be determined by the final FEC and PMA definition

# Receive Characteristics

Description (Inner Eye)	400GBASE-FR8	400GBASE-LR8	Unit
Signaling Rate, each lane	26.6	26.6	GBd
Operating BER*	2.0E-04	2.0E-04	
Receiver reflectance (max)	TBD	TBD	dB
Receiver Sensitivity (OMA), each lane (max)	-10.0	-11.8	dBm
Receiver 3 dB electrical upper cutoff frequency, each lane (max)	21.0	21.0	GHz
Stressed receiver sensitivity (OMA), each lane (max)	TBD	TBD	dBm
Conditions of stressed receiver sensitivity test	TBD	TBD	

\* The exact operating BER will be determined by the final FEC and PMA definition

# Illustrative Link Power Budgets

Parameter	400GBASE-FR8	400GBASE-LR8	Unit
Reach	2	10	km
Power Budget (for maximum TDP)	11.0	13.5	dB
Operating Distance	2.0	10.0	km
Channel Insertion Loss	4.0	6.3	dB
Maximum Discrete Reflectance	TBD	TBD	dB
Allocation for Penalties* (for maximum TDP)	2.0	2.2	dB
Allocation for Modulation Penalties	5.0	5.0	dB

\* Includes MPI penalty. As with all other parameters, it is subject to change in Task Force review.

# WDM Lane Assignments

Lane	Center Frequency THz	Center Wavelength nm	Wavelength Range nm
L0	235.4	1273.55	1272.55 to 1274.54
L1	234.6	1277.89	1276.89 to 1278.89
L2	233.8	1282.26	1281.25 to 1283.28
L3	233.0	1286.66	1285.65 to 1287.69
L4	231.4	1295.56	1294.53 to 1296.59
L5	230.6	1300.05	1299.02 to 1301.09
L6	229.8	1304.58	1303.54 to 1305.63
L7	229.0	1309.14	1308.09 to 1310.19

# Optical Margin

Description (Inner Eye)	400GBASE-FR8	400GBASE-LR8	Unit
Receiver Sensitivity (OMA), each lane, pre-DeMux (max)	-10.0	-11.8	dBm
DeMux Loss	3.0	3.0	dB
Cross-talk penalty	0.3	0.3	dB
Receiver Sensitivity (OMA), each lane, post-DeMux (max)	-13.3	-15.1	dBm
Receiver Sensitivity (OMA) single lane (typical measured)	-17	-17	dBm
Optical Margin	3.7	1.9	dB

# Recommendations

---

- Adopt 8x50G PAM-4 WDM duplex SMF architecture for P802.3bs 2km and 10km SMF PMD objectives as per baseline specifications in this presentation
- Develop the 2km and 10km specifications so that 10km is a higher performance variant of the 2km specification and can be built from upper end of the performance distribution of 2km PMD optical components
- Develop the 10km specification to be compatible with linear APD receivers
- All baseline specification parameters will undergo further analysis and are subject to change by the Task Force

# 2km & 10km PAM-4 PMD Baseline Specs

---

**Thank you**

